International **I⊇R** Rectifier

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IR213(6,62,63,65,66,67,68)(J&S) & PbF

IR2136/IR21362/IR21363/IR21365/IR21366/IR21367/IR21368 (J&S) & (PbF)

600 V three-phase gate driver IC with OCP, Enable, and Fault

Features

- Floating channel designed for bootstrap operation
- Fully operational to +600 V
- Tolerant to negative transient voltage, dV/dt immune
- Gate drive supply range from 10 V to 20 V (IR2136/ IR21368), 11.5 V to 20 V (IR21362D), or 12 V to 20 V (IR21363/IR21365/IR21366/IR21367)
- Undervoltage lockout for all channels
- Over-current shutdown turns off all six drivers
- Independent 3 half-bridge drivers
- Matched propagation delay for all channels
- Cross-conduction prevention logic
- Low side output out of phase with inputs. High side outputs out of phase (IR213(6,63, 65, 66, 67, 68)), or in phase (IR21362) with inputs
- 3.3 V logic compatible
- Lower di/dt gate drive for better noise immunity
- Externally programmable delay for automatic fault clear
- All parts are LEAD-FREE

Packages

28-Lead SOIC   **28-Lead PDIP**

**44-Lead PLCC w/o 12 Leads**
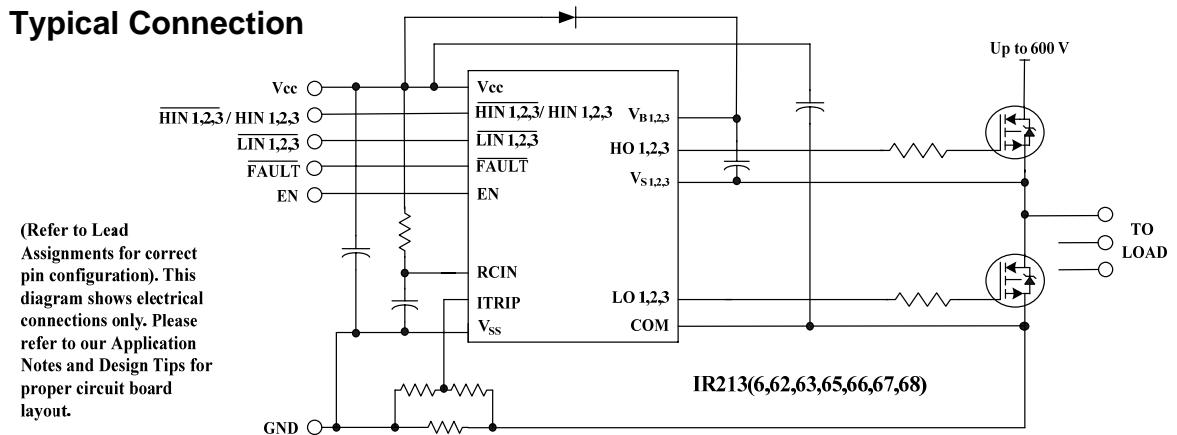
Description

The IR2136x (J&S) are high voltage, high speed power MOSFET and IGBT drivers with three independent high and low side referenced output channels for 3-phase applications. Proprietary HVIC technology enables ruggedized monolithic construction. Logic inputs are compatible with CMOS or LSTTL outputs, down to 3.3 V logic. A current trip function which terminates all six outputs

Feature Comparison: IR213(6,62,63,65,66,67,68)

Part	IR2136	IR21362	IR21363	IR21365	IR21366	IR21367	IR21368
Input Logic	$\overline{HIN}$, LIN	HIN, $\overline{LIN}$	$\overline{HIN}$, LIN	HIN, LIN	$\overline{HIN}$, LIN	$\overline{HIN}$, LIN	$\overline{HIN}$, LIN
Ton (typ.)	400 ns	400 ns	400 ns	400 ns	250 ns	250 ns	400 ns
Toff (typ.)	380ns	380 ns	380 ns	380 ns	180 ns	180 ns	380 ns
V_{IH} (typ.)	2.7 V	2.7 V	2.7 V	2.7 V	2.0 V	2.0 V	2.0 V
V_{IL} (typ.)	1.7 V	1.7 V	1.7 V	1.7 V	1.3 V	1.3 V	1.3 V
Vitrip+	0.46 V	0.46 V	0.46 V	4.3 V	0.46 V	4.3 V	4.3 V
UVCC/BS+	8.9 V	10.4 V	11.2 V	11.2 V	11.2 V	11.2 V	8.9 V
UVCC/BS-	8.2 V	9.4 V	11.0 V	11.0 V	11.0 V	11.0 V	8.2 V

can be derived from an external current sense resistor. An enable function is available to terminate all six outputs simultaneously. An open-drain FAULT signal is provided to indicate that an overcurrent or undervoltage shutdown has occurred. Overcurrent fault conditions are cleared automatically after a delay programmed externally via an RC network connected to the RCIN input. The output drivers feature a high pulse current buffer stage designed for minimum driver cross-conduction. Propagation delays are matched to simplify use in high frequency applications. The floating channels can be used to drive N-channel power MOSFETs or IGBTs in the high side configuration which operates up to 600 V.

Typical Connection

(Refer to Lead Assignments for correct pin configuration). This diagram shows electrical connections only. Please refer to our Application Notes and Design Tips for proper circuit board layout.

IR213(6,62,63,65,66,67,68)

IR213(6,62,63,65,66,67,68)(J&S) & PbF

Absolute Maximum Ratings

Absolute Maximum Ratings indicate sustained limits beyond which damage to the device may occur. All voltage parameters are absolute voltages referenced to COM. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions.

Symbol	Definition		Min	Max	Units
V_S	High side offset voltage		$V_{B\,1,2,3}$ - 25	$V_{B\,1,2,3}$ + 0.3	V
V_B	High side floating supply voltage		-0.3	625	
V_{HO}	High side floating output voltage		$V_{S1,2,3}$ - 0.3	$V_{B\,1,2,3}$ + 0.3	
V_{CC}	Low side and logic fixed supply voltage		-0.3	25	
V_{SS}	Logic ground		V_{CC} - 25	V_{CC} + 0.3	
$V_{LO1,2,3}$	Low side output voltage		-0.3	V_{CC} + 0.3	
V_{IN}	Input voltage LIN, HIN, ITRIP, EN		V_{SS} -0.3	Lower of (V_{SS} + 15) or V_{CC} + 0.3)	
V_{RCIN}	RCIN input voltage		V_{SS} -0.3	V_{CC} + 0.3	
V_{FLT}	$\overline{FAULT}$ output voltage		V_{SS} -0.3	V_{CC} + 0.3	
dV/dt	Allowable offset voltage slew rate		—	50	V/ns
P_D	Package power dissipation @ T_A ≤ +25 °C	(28 lead PDIP)	—	1.5	W
		(28 lead SOIC)	—	1.6	
		(44 lead PLCC)	—	2.0	
Rth_{JA}	Thermal resistance, junction to ambient	(28 lead PDIP)	—	83	°C/W
		(28 lead SOIC)	—	78	
		(44 lead PLCC)	—	63	
T_J	Junction temperature		—	150	°C
T_S	Storage temperature		-55	150	
T_L	Lead temperature (soldering, 10 seconds)		—	300	

Recommended Operating Conditions

The input/output logic-timing diagram is shown in Fig. 1. For proper operation the device should be used within the recommended conditions. All voltage parameters are absolute referenced to COM. The V_S offset ratings are tested with all supplies biased at a 15 V differential.

Symbol	Definition		Min	Max	Units
$V_{B1,2,3}$	High side floating supply voltage	IR213(6,68)	$V_{S1,2,3}$ +10	$V_{S1,2,3}$ + 20	V
		IR21362	$V_{S1,2,3}$ +11.5	$V_{S1,2,3}$ + 20	
		IR213(6,63,65,66,67)	$V_{S1,2,3}$ +12	$V_{S1,2,3}$ + 20	
$V_{S\,1,2,3}$	High side floating supply offset voltage		Note 1	600	
$V_{HO\,1,2,3}$	High side output voltage		$V_{S1,2,3}$	$V_{B1,2,3}$	
$V_{LO1,2,3}$	Low side output voltage		0	V_{CC}	
V_{CC}	Low side and logic fixed supply voltage	IR213(6,68)	10	20	
		IR21362	11.5	20	
		IR213(6,63,65,66,67)	12	20	
V_{SS}	Logic ground		-5	5	
V_{FLT}	$\overline{FAULT}$ output voltage		V_{SS}	V_{CC}	
V_{RCIN}	RCIN input voltage		V_{SS}	V_{CC}	

Note 1: Logic operational for V_S of (COM - 5 V) to (COM + 600 V). Logic state held for V_S of (COM - 5 V) to (COM – V_{BS}). (Please refer to the Design Tip DT97-3 for more details).
Note 2: All input pins and the ITRIP and EN pins are internally clamped with a 5.2 V zener diode.

Recommended Operating Conditions - (Continued)

The input/output logic-timing diagram is shown in Fig. 1. For proper operation the device should be used within the recommended conditions. All voltage parameters are absolute referenced to COM. The V_S offset ratings are tested with all supplies biased at a 15 V differential.

Symbol	Definition	Min	Max	Units
V_{ITRIP}	ITRIP input voltage	V_{SS}	V_{SS} + 5	V
V_{IN}	Logic input voltage $\overline{LIN}$, $\overline{HIN}$ (IR213(6,63,65,66,67,68)), HIN (IR21362), EN	V_{SS}	V_{SS} + 5	
T_A	Ambient temperature	-40	125	°C

Note 2: All input pins and the ITRIP and EN pins are internally clamped with a 5.2 V zener diode.

Static Electrical Characteristics

V_{BIAS} (V_{CC},$V_{BS1,2,3}$) = 15 V unless otherwise specified. The V_{IN}, V_{TH}, and I_{IN} parameters are referenced to V_{SS} and are applicable to all six channels ($\overline{HIN1,2,3}$ and $\overline{LIN1,2,3}$). The V_O and I_O parameters are referenced to COM and $V_{S1,2,3}$ and are applicable to the respective output leads: HO1,2,3 and LO1,2,3.

Symbol	Definition		Min	Typ	Max	Units	Test Conditions
V_{IH}	Logic "0" input voltage $\overline{LIN1,2,3}$, $\overline{HIN1,2,3}$ IR213(6,63,65) Logic "1" input voltage HIN1,2,3 IR21362		3.0	—	—	V	
	Logic "0" input voltage $\overline{LIN1,2,3}$, $\overline{HIN1,2,3}$ IR213(66,67,68)		2.5	—	—		
V_{IL}	Logic "1" input Voltage $\overline{LIN1,2,3}$, $\overline{HIN1,2,3}$ IR213(6,63,65) Logic "0" input voltage HIN1,2,3 IR21362		—	—	0.8		
	Logic "0" input voltage $\overline{LIN1,2,3}$, $\overline{HIN1,2,3}$ IR213(66,67,68)		—	—			
$V_{EN,TH+}$	Enable positive going threshold		—	—	3		
$V_{EN,TH-}$	Enable negative going threshold		0.8	—	—		
$V_{IT,TH+}$	ITRIP positive going threshold	IR2136(2)(3)(6)	0.37	0.46	0.55		
		IR21365(7)(8)	3.85	4.30	4.75		
$V_{IT,HYS}$	ITRIP input hysteresis	IR2136(2)(3)(6)	—	0.07	—		
		IR21365(7)(8)	—	.15	—		
$V_{RCIN, TH+}$	RCIN positive going threshold		—	8	—		
$V_{RCIN, HYS}$	RCIN input hysteresis		—	3	—		
V_{OH}	High level output voltage, V_{BIAS} - V_O		—	0.9	1.4		Io = 20 mA
V_{OL}	Low level output voltage, V_O		—	0.4	0.6		
V_{CCUV+} V_{BSUV+}	V_{CC} and V_{BS} supply undervoltage positive going threshold	IR2136(8)	8.0	8.9	9.8		
		IR21362	9.6	10.4	11.2		
		IR21363(5)(6)(7)	10.6	11.1	11.6		

Static Electrical Characteristics - (Continued)

V_{BIAS} (V_{CC},$V_{BS1,2,3}$) = 15 V unless otherwise specified. The V_{IN}, V_{TH}, and I_{IN} parameters are referenced to V_{SS} and are applicable to all six channels ($\overline{HIN1,2,3}$ and $\overline{LIN1,2,3}$). The V_O and I_O parameters are referenced to COM and $V_{S1,2,3}$ and are applicable to the respective output leads: HO1,2,3 and LO1,2,3.

Symbol	Definition		Min	Typ	Max	Units	Test Conditions
V_{CCUV-} V_{BSUV-}	V_{CC} and V_{BS} supply undervoltage negative going threshold	IR2136(8)	7.4	8.2	9.0	V	
		IR21362	8.6	9.4	10.2		
		IR2136(3,5,6,7)	10.4	10.9	11.4		
V_{CCUVH} V_{BSUVH}	V_{CC} and V_{BS} supply undervoltage lockout hysteresis	IR2136	0.3	0.7	—		
		IR21362	0.5	1.0	—		
		IR2136(3,5)	—	0.2	—		
I_{LK}	Offset supply leakage current		—	—	50	µA	$V_{B1,2,3}$ = $V_{S1,2,3}$ = 600 V
I_{QBS}	Quiescent V_{BS} supply current		—	70	120		V_{IN} = 0 V or 5 V
I_{QCC}	Quiescent V_{CC} supply current		—	1.6	2.3	mA	
$V_{IN,CLAMP}$	Input clamp voltage (HIN, LIN, ITRIP and EN)		4.9	5.2	5.5	V	I_{IN} =100 µA
I_{LIN+}	Input bias current (LOUT = HI)	IR2136(2,3,5)	—	200	300		V_{LIN} = 5 V
		IR2136(6,7,8)	—	30	100		
I_{LIN-}	Input bias current (LOUT = LO)	IR2136(2,3,5)	—	100	220		V_{LIN} = 0 V
		IR2136(6,7,8)	—	0	1		
I_{HIN+}	Input bias current (HOUT = HI)	IR2136(3,5)	—	200	300		V_{HIN} = 5 V
		IR21362	—	30	100		
		IR2136(6,7,8)	—	30	100		
I_{HIN-}	Input bias current (HOUT = LO)	IR2136(3,5)	—	100	220	µA	V_{HIN} = 0 V
		IR2136(2,6,7,8)	—	0	1		
I_{ITRIP+}	"High" ITRIP input bias current		—	30	100		V_{ITRIP} = 5 V
I_{ITRIP-}	"Low" ITRIP input bias current		—	0	1		V_{ITRIP} = 0 V
I_{EN+}	"High" ENABLE input bias current		—	30	100		V_{ENABLE} = 5 V
I_{EN-}	"Low" ENABLE input bias current		—	0	1		V_{ENABLE} =0 V
I_{RCIN}	RCIN input bias current		—	0	1		Vrcin= 0 V or 15 V
I_{O+}	Output high short circuit pulsed current		120	200	—	mA	Vo =0 V, PW ≤10 µs
I_{O-}	Output low short circuit pulsed current		250	350	—		Vo =15 V, PW ≤10 µs
R_{on_RCIN}	RCIN low on resistance		—	50	100	Ω	
R_{on_FAULT}	$\overline{FAULT}$ low on resistance		—	50	100		

Dynamic Electrical Characteristics

$V_{CC} = V_{BS} = V_{BIAS} = 15$ V, $V_{S1,2,3} = V_{SS} = $ COM, $T_A = 25$ °C and CL = 1000 pF unless otherwise specified.

Symbol	Definition		Min	Typ	Max	Units	Test Conditions
t_{on}	Turn-on propagation delay	IR2136(2,3,5,8)	300	425	550	ns	$V_{IN} = 0$ V & 5 V
		IR2136(6,7)	—	250	—		
t_{off}	Turn-off propagation delay	IR2136(2,3,5,8)	250	400	550		
		IR2136(6,7)	—	180	—		
t_r	Turn-on rise time		—	125	190		
t_f	Turn-off fall time		—	50	75		
t_{EN}	ENABLE low to output shutdown propagation delay	IR2136(2,3,5,8)	300	450	600		$V_{IN}, V_{EN} = 0$ V or 5 V
		IR2136(6,7)	100	250	400		
t_{ITRIP}	ITRIP to output shutdown propagation delay		500	750	1000		$V_{ITRIP} = 5$ V
t_{bl}	ITRIP blanking time		100	150	—		$V_{IN} = 0$ V or 5 V $V_{ITRIP} = 5$ V
t_{FLT}	ITRIP to $\overline{FAULT}$ propagation delay		400	600	800		
t_{FILIN}	Input filter time (HIN, LIN) (IR213(6,62,63,65,68) only)		100	200	—		$V_{IN} = 0$ V & 5 V
t_{FLTCLR}	FAULT clear time RCIN: R = 2 MΩ, C = 1 nF		1.3	1.65	2	ms	$V_{IN} = 0$ V or 5 V $V_{ITRIP} = 0$ V
DT	Deadtime		220	290	360		$V_{IN} = 0$ V & 5 V
MT	Matching delay ON and OFF		—	40	75	ns	External dead time >400 ns
MDT	Matching delay, max (t_{on}, t_{off}) – min (t_{on}, t_{off}), (t_{on}, t_{off} are applicable to all 3 channels)		—	25	70		
PM	Output pulse width matching (pwin-pwout) (Fig.2)		—	40	75		

Note: For high side PWM, HIN pulse width must be ≥ 1 µs.
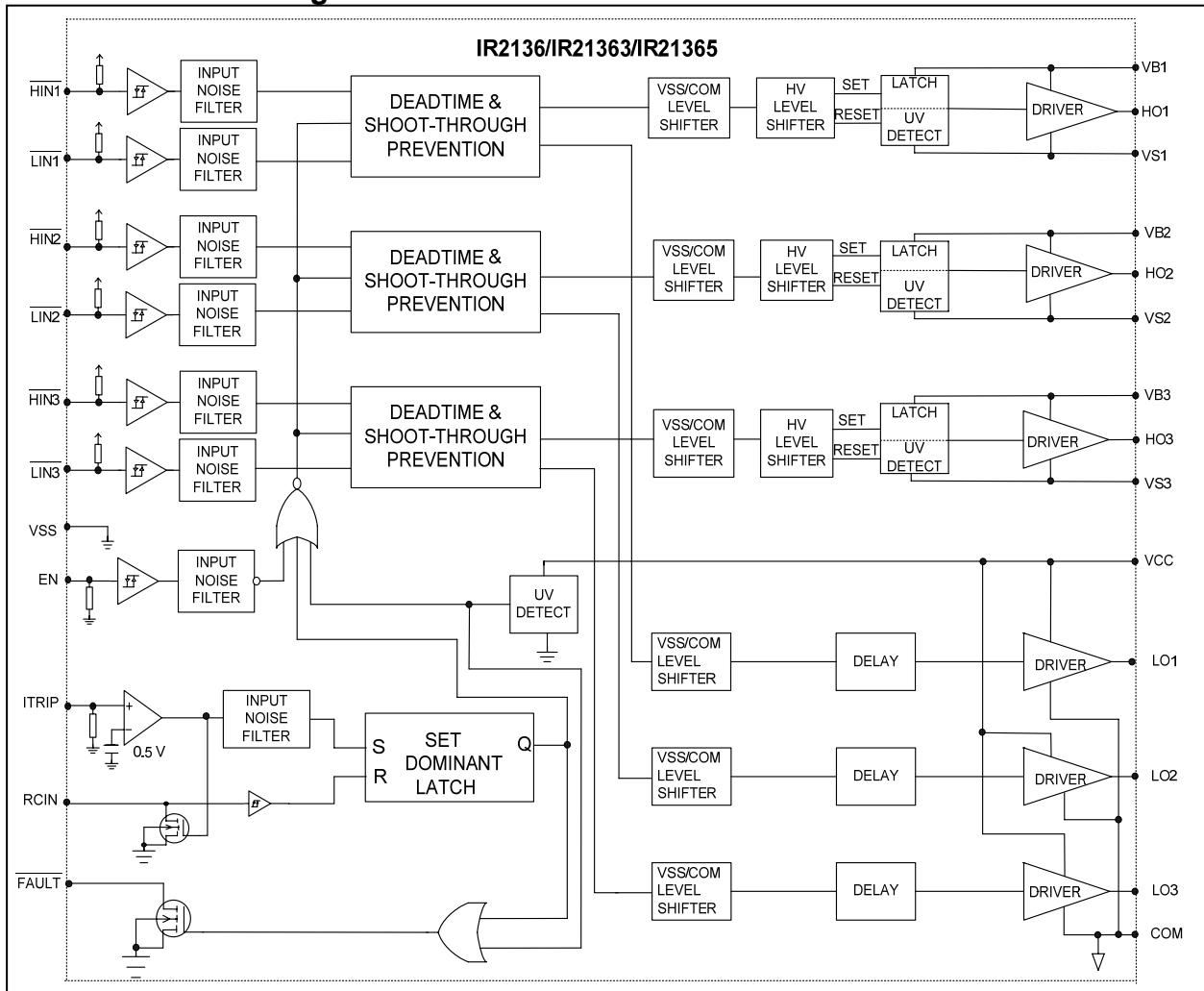
VCC	VBS	ITRIP	ENABLE	FAULT	LO1,2,3	HO1,2,3
<UVCC	X	X	X	0 (note 1)	0	0
15 V	<UVBS	0 V	5 V	high imp	LIN1,2,3	0
15 V	15 V	0 V	5 V	high imp	LIN1,2,3	HIN1,2,3
15 V	15 V	>V_{ITRIP}	5 V	0 (note 2)	0	0
15 V	15 V	0 V	0 V	high imp	0	0

Note 1: A shoot-through prevention logic prevents LO1,2,3 and HO1,2,3 for each channel from turning on simultaneously.
Note 2: UVCC is not latched, when $V_{CC} > UV_{CC}$, FAULT returns to high impedance.
Note 3: When ITRIP < V_{ITRIP}, FAULT returns to high-impedance after RCIN pin becomes greater than 8 V (@ V_{CC} = 15 V).
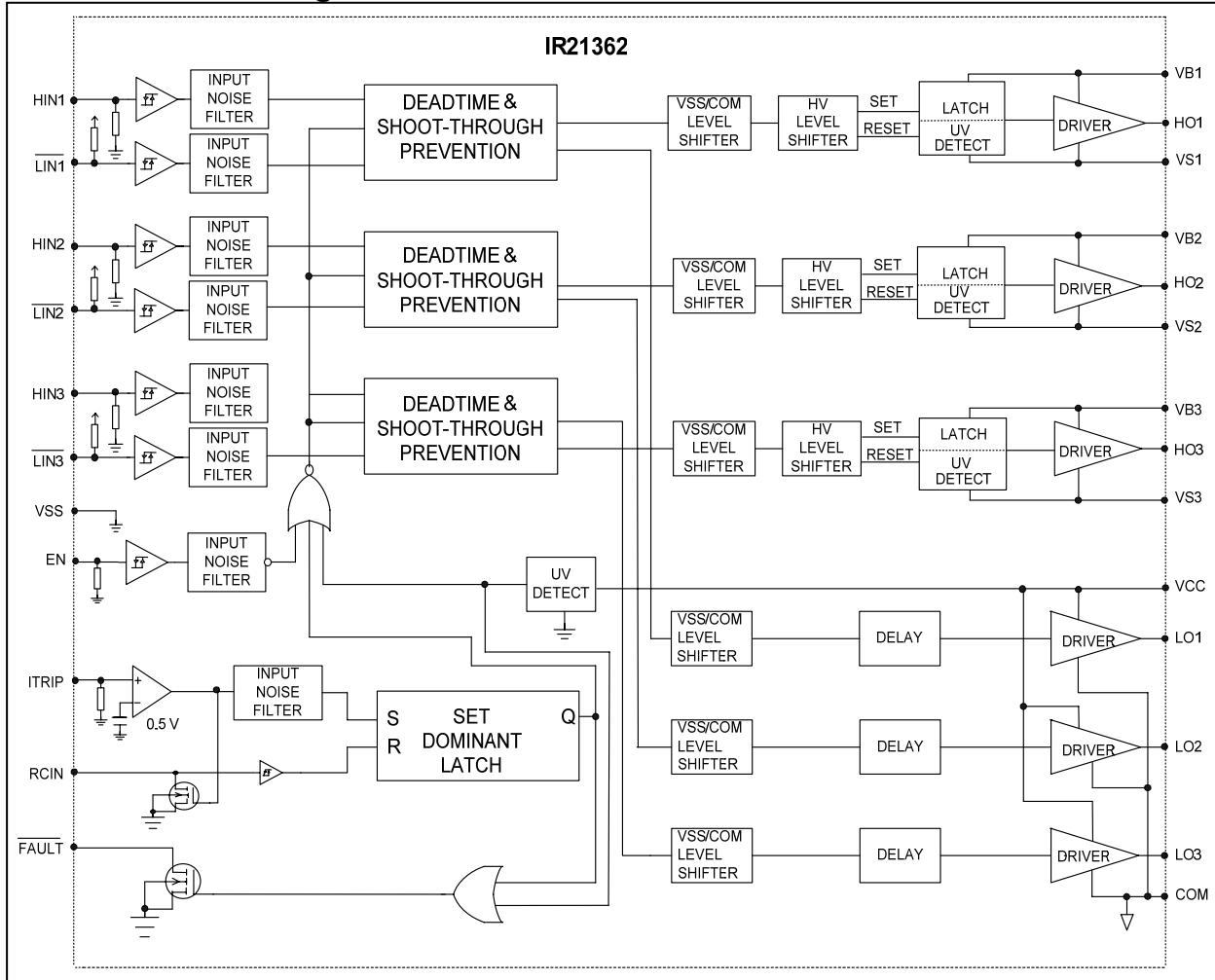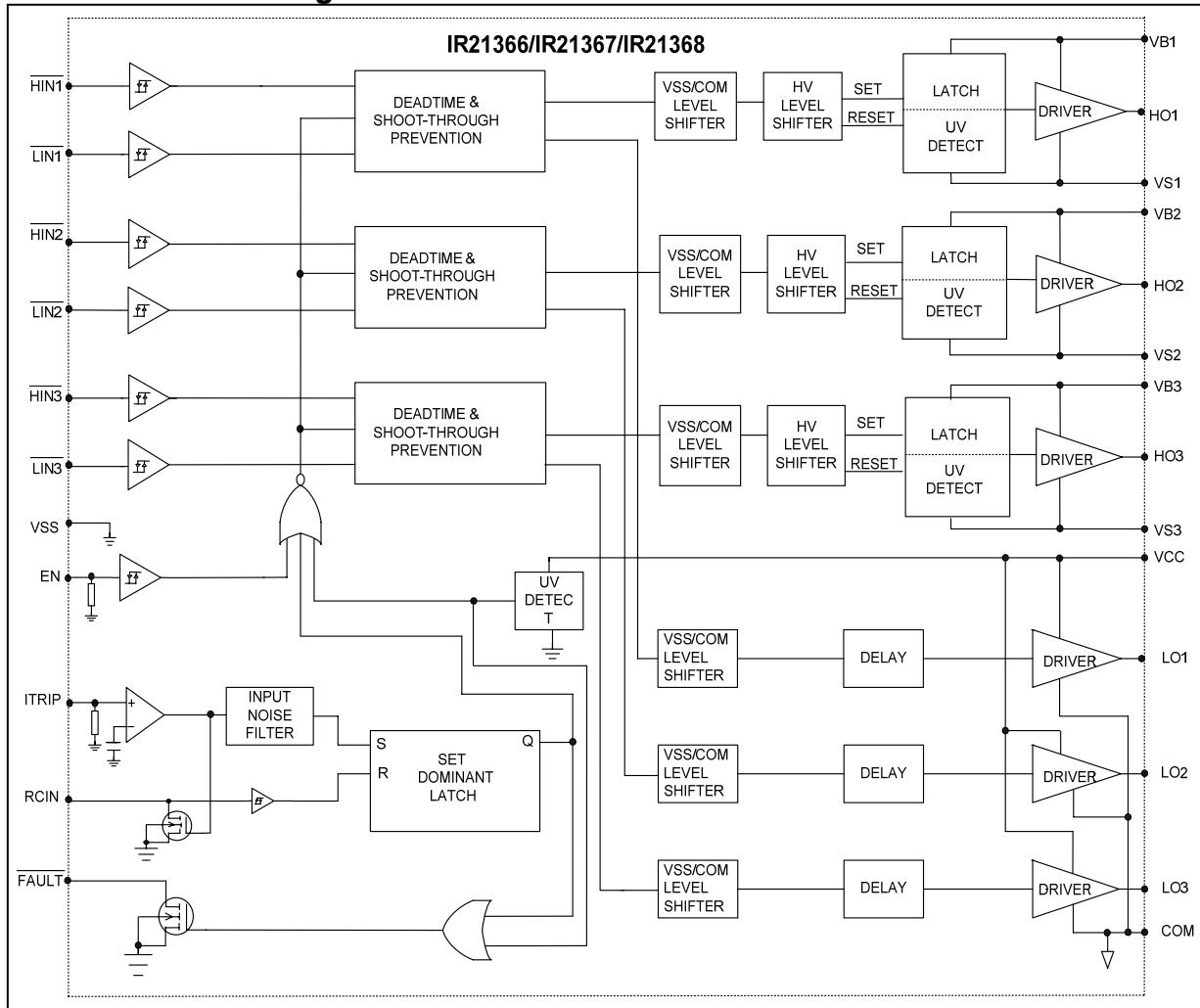
Functional Block Diagram

Functional Block Diagram

Functional Block Diagram

IR213(6,62,63,65,66,67,68)(J&S) & PbF
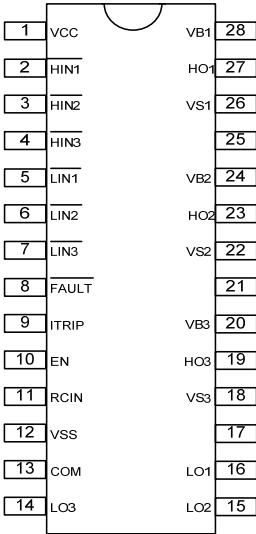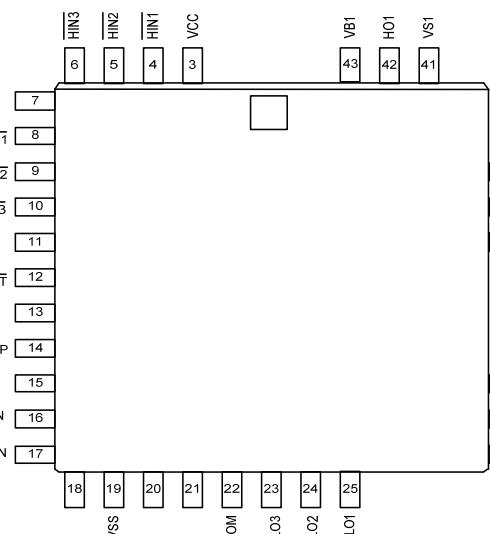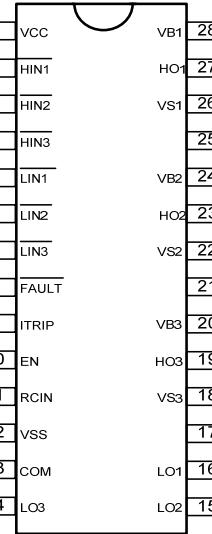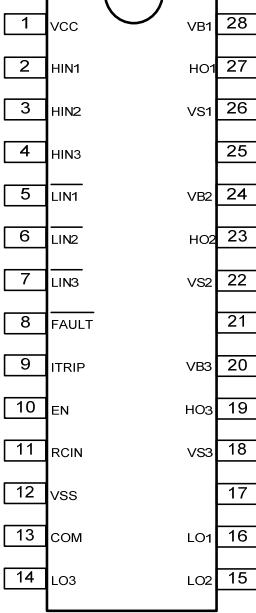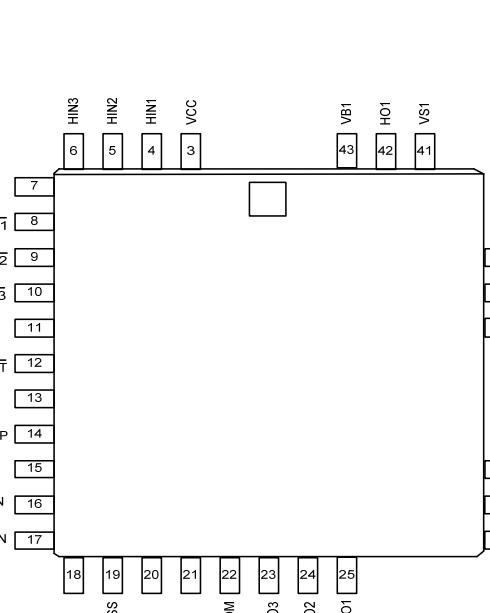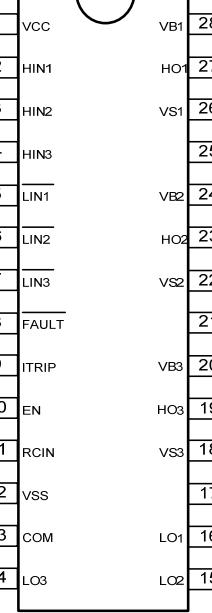
Lead Definitions

Symbol	Description
V_{CC}	Low side and logic fixed supply
V_{SS}	Logic ground
$\overline{HIN1,2,3}$ HIN1,2,3	Logic inputs for high side gate driver outputs (HO1,2,3), out of phase [IR213(6,63,65,66,67,68)] Logic inputs for high side gate driver outputs (HO1,2,3), in phase (IR21362)
$\overline{LIN1,2,3}$	Logic input for low side gate driver outputs (LO1,2,3), out of phase
FAULT	Indicates over-current (ITRIP) or low-side undervoltage lockout has occurred. Negative logic, open-drain output
EN	Logic input to enable I/O functionality. I/O logic functions when ENABLE is high (i.e., positive logic) No effect on FAULT and not latched
ITRIP	Analog input for overcurrent shutdown. When active, ITRIP shuts down outputs and activates FAULT and RCIN low. When ITRIP becomes inactive, FAULT stays active low for an externally set time T_{FLTCLR}, then automatically becomes inactive (open-drain high impedance).
RCIN	External RC network input used to define FAULT CLEAR delay, $T_{FLTCLR,}$ approximately equal to R*C. When RCIN>8 V, the FAULT pin goes back into open-drain high-impedance
COM	Low side gate drivers return
$V_{B1,2,3}$	High side floating supply
HO1,2,3	High side gate driver outputs
$V_{S1,2,3}$	High voltage floating supply return
LO1,2,3	Low side gate driver outputs

Note: All input pins and the ITRIP pin are internally clamped with a 5.2 V zener diode.

International
I⊕R Rectifier

Lead Assignments

28 Lead PDIP	44 Lead PLCC w/o 12 leads	28 Lead SOIC (wide body)
IR213(6, 63, 65, 66, 67,68)	IR213(6, 63, 65, 66, 67,68)J	IR213(6, 63, 65, 66, 67,68)S

28 Lead PDIP

1	VCC	VB1	28
2	HIN1	HO1	27
3	HIN2	VS1	26
4	HIN3		25
5	LIN1	VB2	24
6	LIN2	HO2	23
7	LIN3	VS2	22
8	FAULT		21
9	ITRIP	VB3	20
10	EN	HO3	19
11	RCIN	VS3	18
12	VSS		17
13	COM	LO1	16
14	LO3	LO2	15

44 Lead PLCC w/o 12 leads

Top pins: HIN3(6), HIN2(5), HIN1(4), VCC(3), VB1(43), HO1(42), VS1(41)
Left pins: (7), LIN1(8), LIN2(9), LIN3(10), (11), FAULT(12), (13), ITRIP(14), (15), EN(16), RCIN(17)
Right pins: VB2(37), HO2(36), VS2(35), VB3(31), HO3(30), VS3(29)
Bottom pins: (18), VSS(19), (20), (21), COM(22), LO3(23), LO2(24), LO1(25)

28 Lead SOIC (wide body)

1	VCC	VB1	28
2	HIN1	HO1	27
3	HIN2	VS1	26
4	HIN3		25
5	LIN1	VB2	24
6	LIN2	HO2	23
7	LIN3	VS2	22
8	FAULT		21
9	ITRIP	VB3	20
10	EN	HO3	19
11	RCIN	VS3	18
12	VSS		17
13	COM	LO1	16
14	LO3	LO2	15

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28 Lead PDIP	44 Lead PLCC w/o 12 leads	28 Lead SOIC (wide body)
IR21362	IR21362J	IR21362S

28 Lead PDIP

1	VCC	VB1	28
2	HIN1	HO1	27
3	HIN2	VS1	26
4	HIN3		25
5	LIN1	VB2	24
6	LIN2	HO2	23
7	LIN3	VS2	22
8	FAULT		21
9	ITRIP	VB3	20
10	EN	HO3	19
11	RCIN	VS3	18
12	VSS		17
13	COM	LO1	16
14	LO3	LO2	15

44 Lead PLCC w/o 12 leads

Top pins: HIN3(6), HIN2(5), HIN1(4), VCC(3), VB1(43), HO1(42), VS1(41)
Left pins: (7), LIN1(8), LIN2(9), LIN3(10), (11), FAULT(12), (13), ITRIP(14), (15), EN(16), RCIN(17)
Right pins: VB2(37), HO2(36), VS2(35), VB3(31), HO3(30), VS3(29)
Bottom pins: (18), VSS(19), (20), (21), COM(22), LO3(23), LO2(24), LO1(25)

28 Lead SOIC (wide body)

1	VCC	VB1	28
2	HIN1	HO1	27
3	HIN2	VS1	26
4	HIN3		25
5	LIN1	VB2	24
6	LIN2	HO2	23
7	LIN3	VS2	22
8	FAULT		21
9	ITRIP	VB3	20
10	EN	HO3	19
11	RCIN	VS3	18
12	VSS		17
13	COM	LO1	16
14	LO3	LO2	15

Fig. 1. Input/Output Timing Diagram
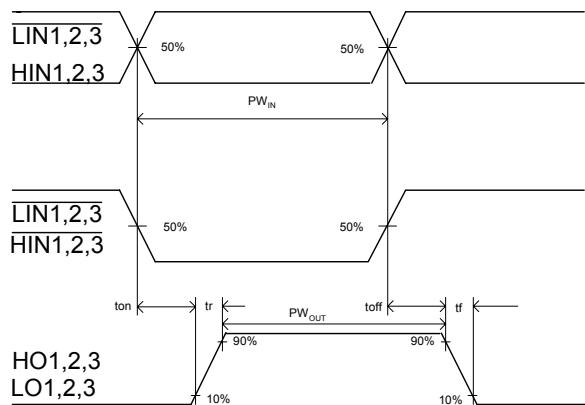
Fig. 2. Switching Time Waveforms
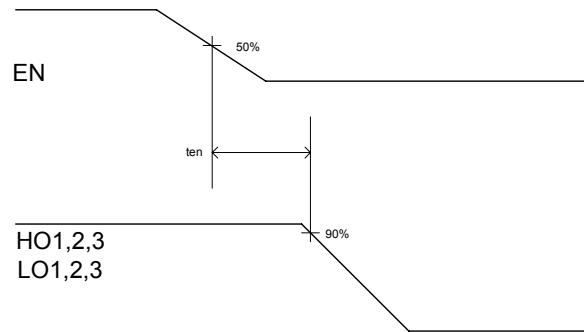
Fig. 3. Output Enable Timing Waveform
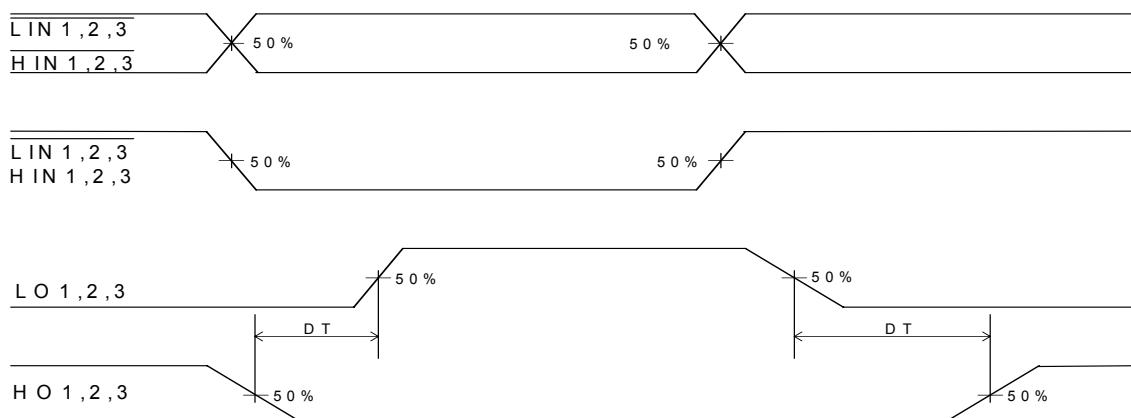
Fig. 4. Internal Deadtime Timing Waveforms
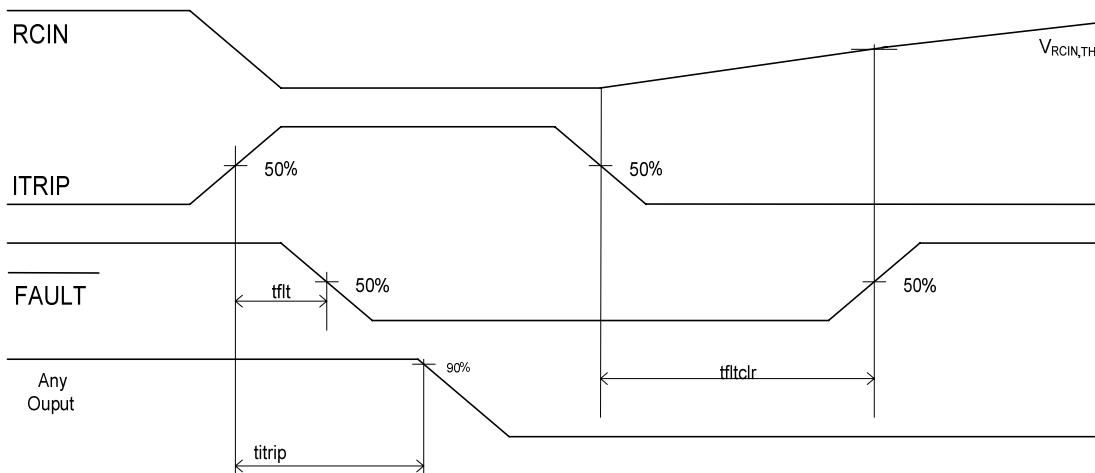
Fig. 5. ITRIP/RCIN Timing Waveforms
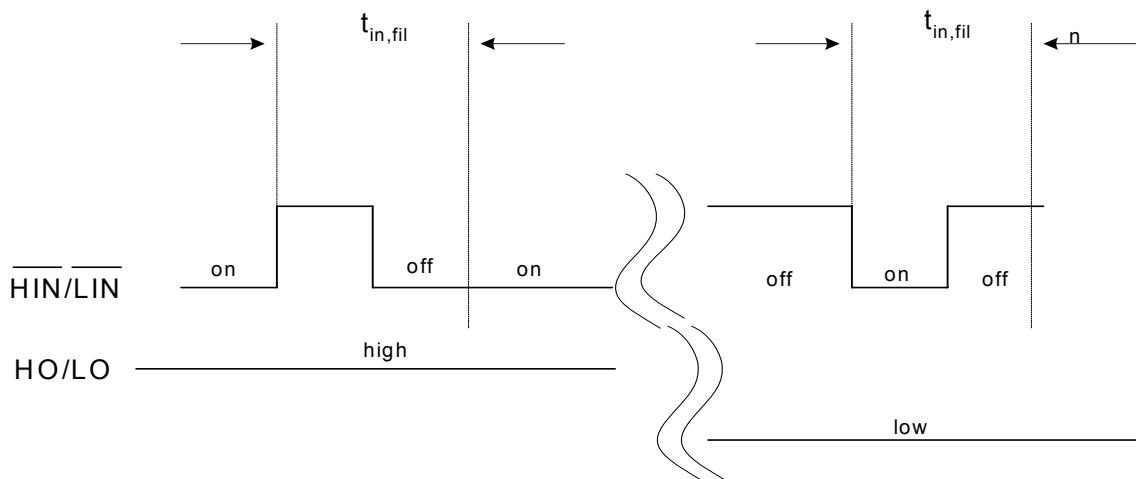
Fig. 6. Input Filter Function
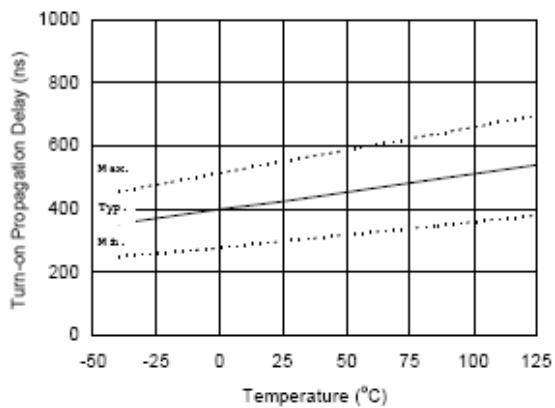
Figure 6A. Turn-on Propagation Delay vs.
Temperature
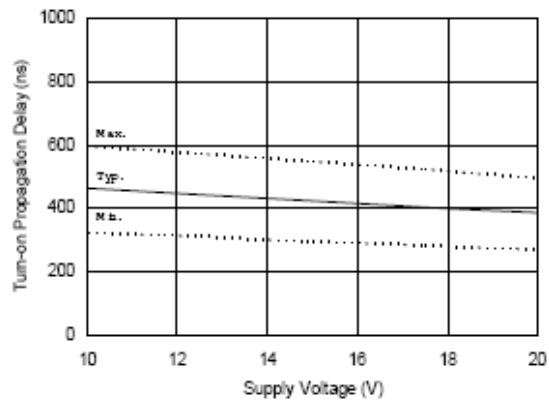
Figure 6B. Turn-on Propagation Delay vs.
Supply Voltage
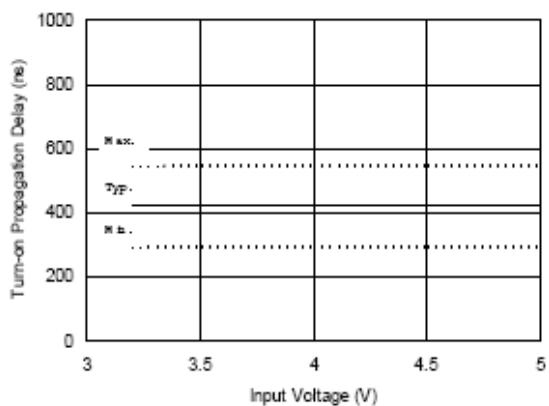
Figure 6C. Turn-on Propagation Delay vs.
Input Voltage
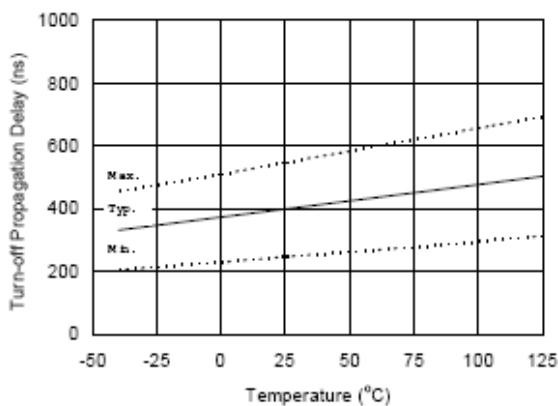
Figure 7A. Turn-off Propagation Delay vs.
Temperature
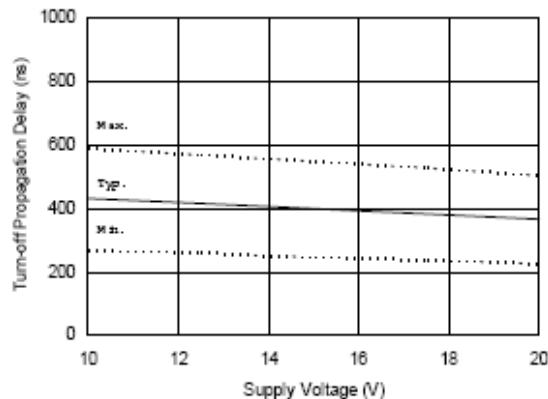
Figure 7B. Turn-off Propagation Delay vs.
Supply Voltage
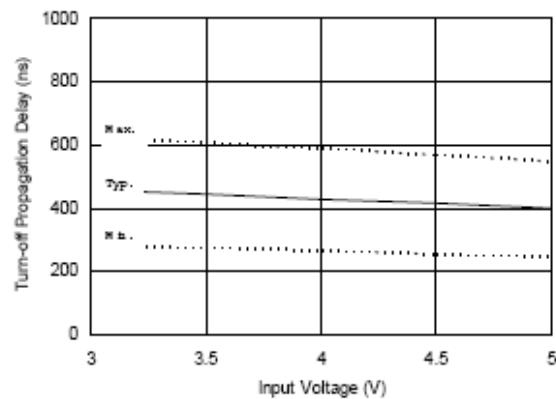
Figure 7C. Turn-off Propagation Delay vs.
Input Voltage
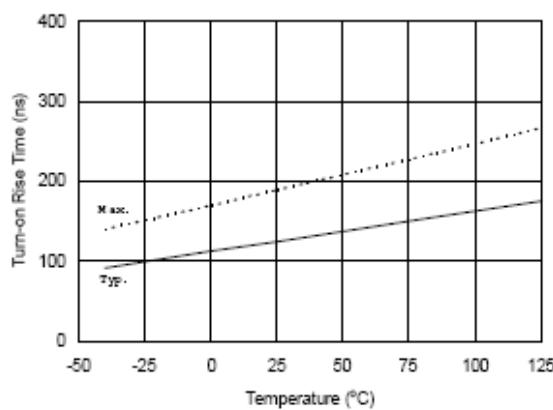
Figure 8A. Turn-on Rise Time vs. Temperature
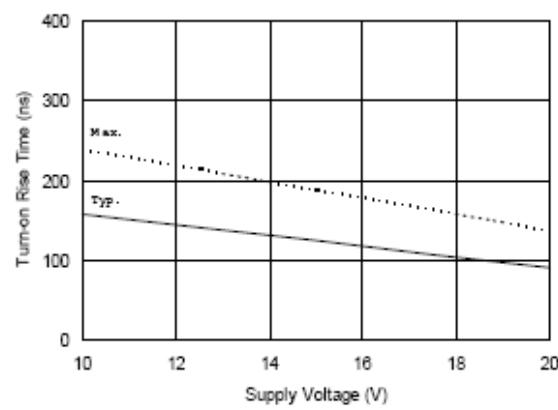
Figure 8B. Turn-on Rise Time vs. Supply Voltage
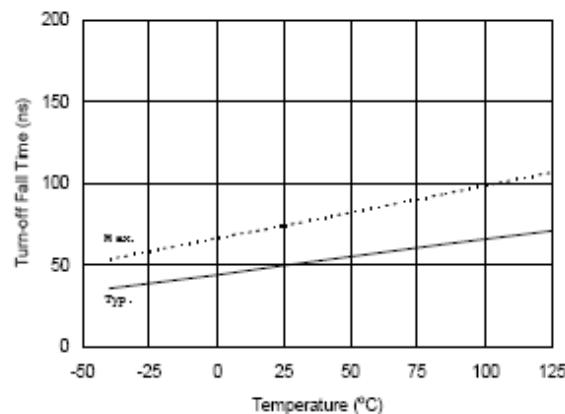
Figure 9A. Turn-off Fall Time vs. Temperature
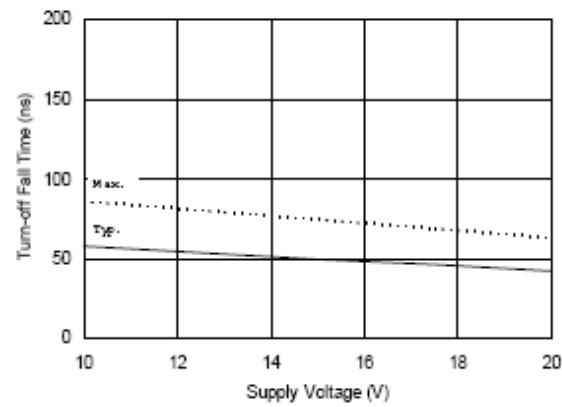
Figure 9B. Turn-off Fall Time vs. Supply Voltage
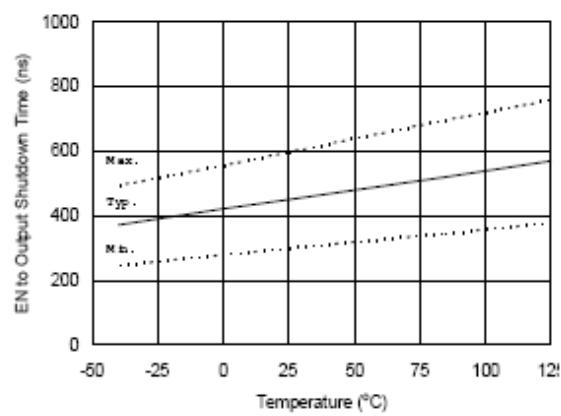
Figure 10A. EN to Output Shutdown Time vs. Temperature
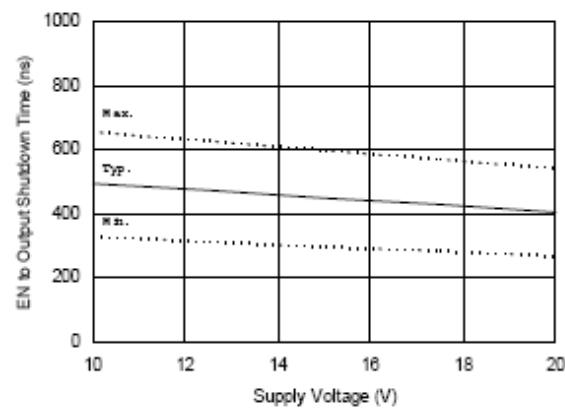
Figure 10B. EN to Output Shutdown Time vs. Supply Voltage
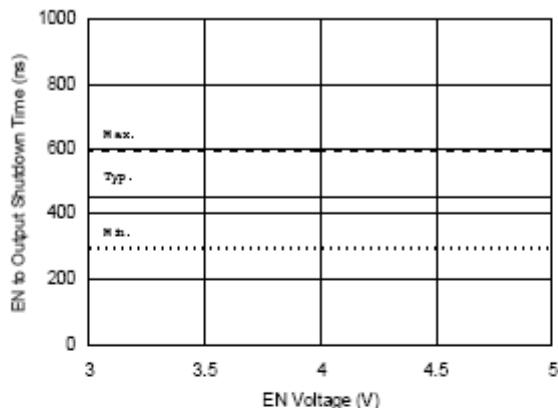
Figure 10C. EN to Output Shutdown Time
vs. EN Voltage
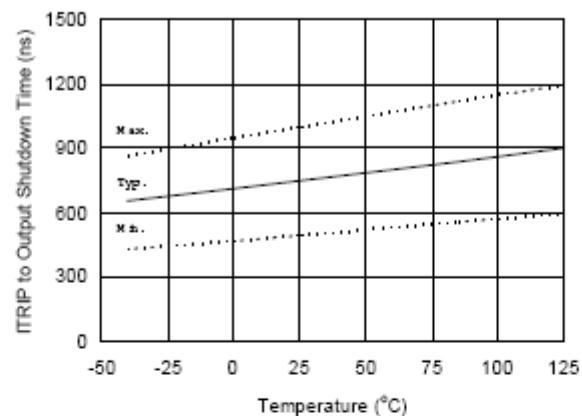
Figure 11A. ITRIP to Output Shutdown Time vs.
Temperature
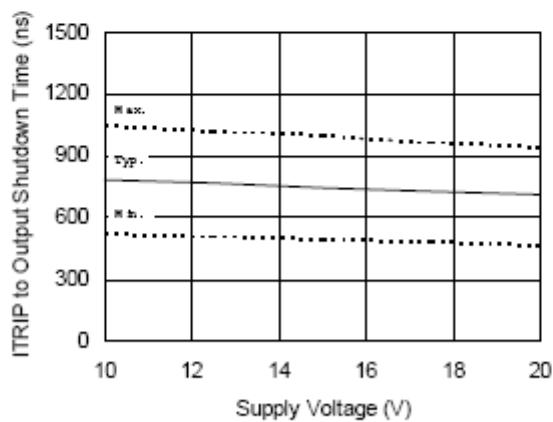
Figure 11B. ITRIP to Output Shutdown
Time vs. Supply Voltage
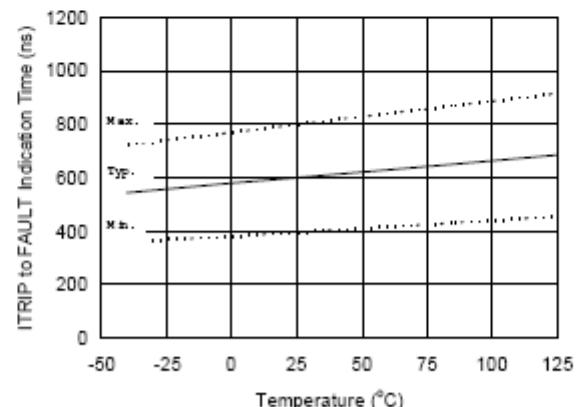
Figure 12A. ITRIP to FAULT Indication Time vs.
Temperature
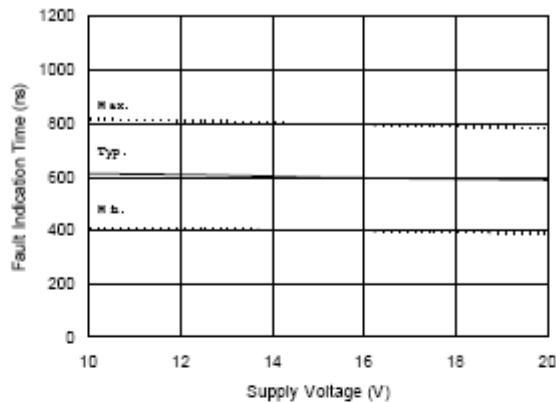
Figure 12B. ITRIP to FAULT Indication Time vs. Supply Voltage
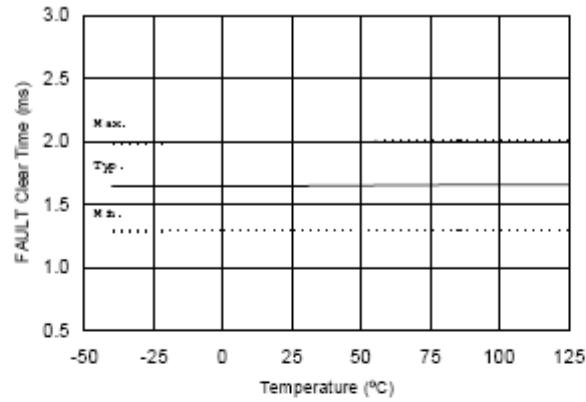
Fig13A. FAULT Clear Time vs. Temperature
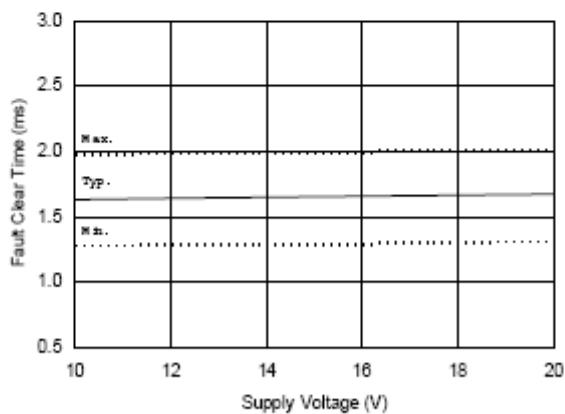
Figure 13B. FAULT Clear Time vs. Supply Voltage
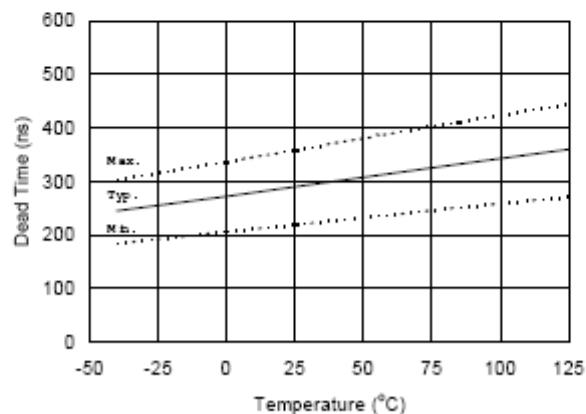
Figure 14A. Dead Time vs. Temperature
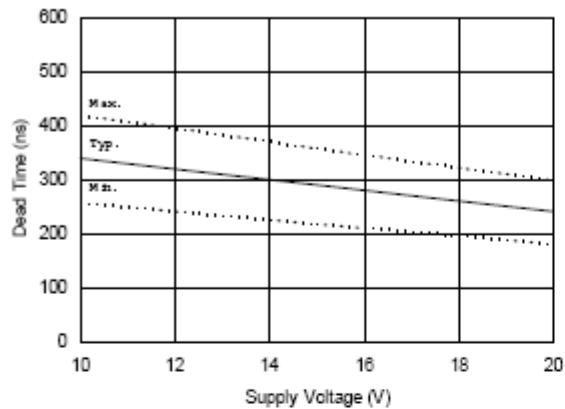
Figure 14B. Dead Time Time vs. Supply Voltage
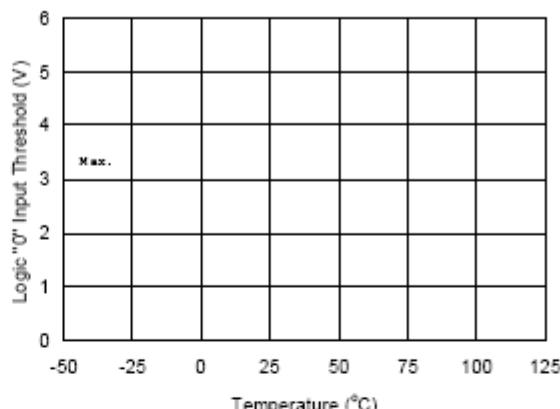
Figure 15A. Logic "0" Input Threshold vs.
Temperature
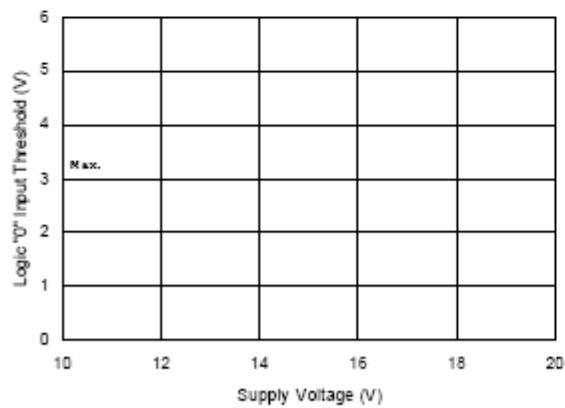
Figure 15B. Logic "0" Input Threshold vs.
Supply Voltage
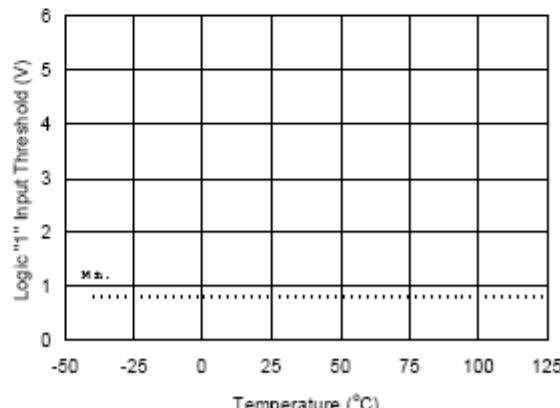
Figure 16A. Logic "1" Input Threshold vs.
Temperature
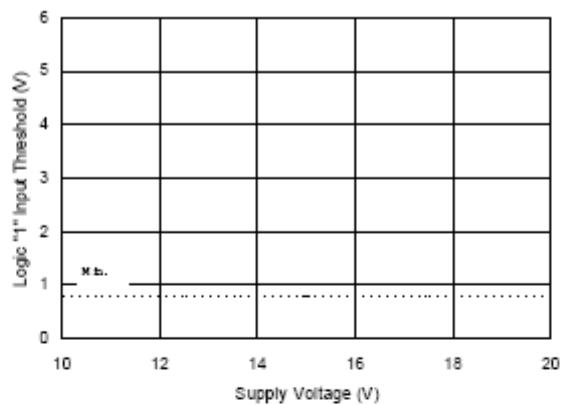
Figure 16B. Logic "1" Input Threshold vs.
Supply Voltage
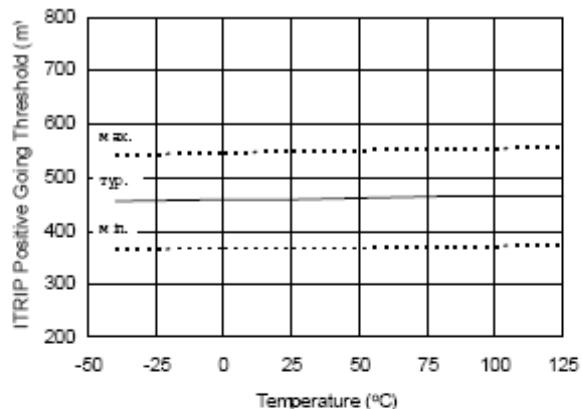
Figure 17A. ITRIP Positive Going Threshold vs.
Temperature (IR2136/21362/21363/IR21366 Only)
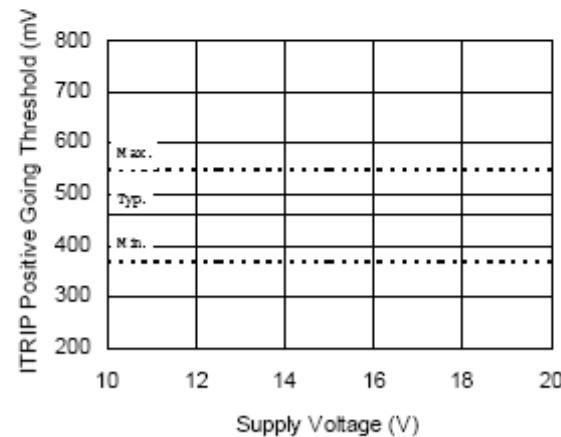
Figure 17B. ITRIP Positive Going Threshold vs.
Supply Voltage (IR2136/21362/21363/IR21366 Only)
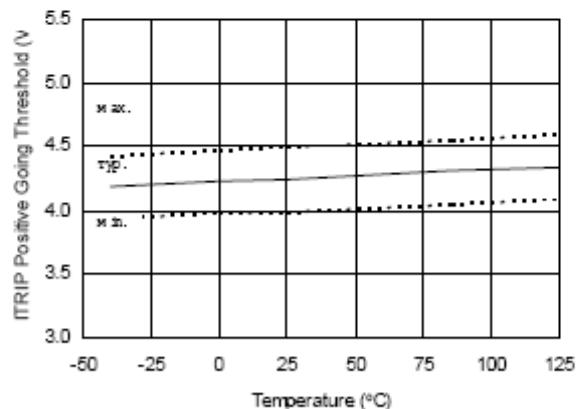
Figure 17C. ITRIP Positive Going Threshold vs.
Temperature (IR21365/IR21367/IR21368 Only)
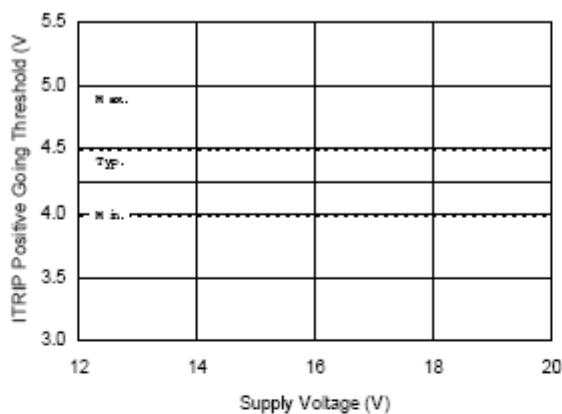
Figure 17D. ITRIP Positive Going Threshold vs.
Supply Voltage (IR21365/IR21367/IR21368 Only)
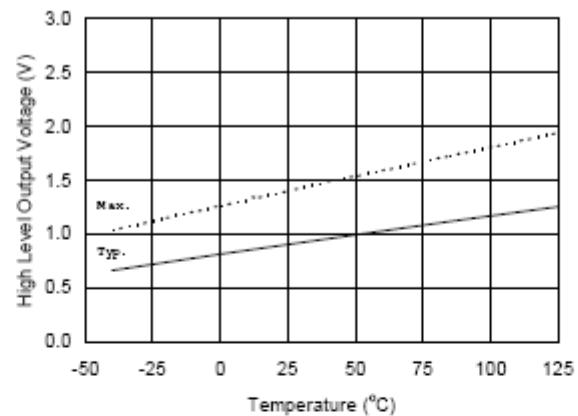
Figure 18A. High Level Output vs. Temperature
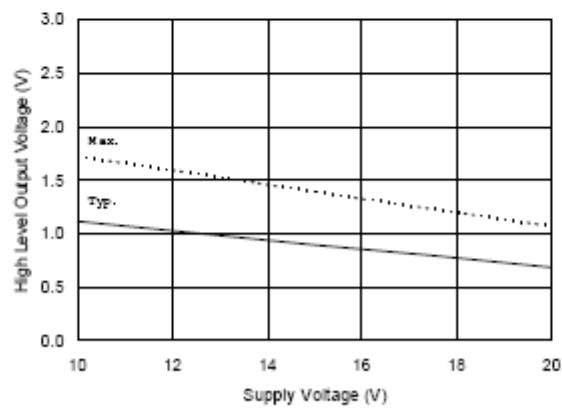
Figure 18B. High Level Output vs. Supply Voltage
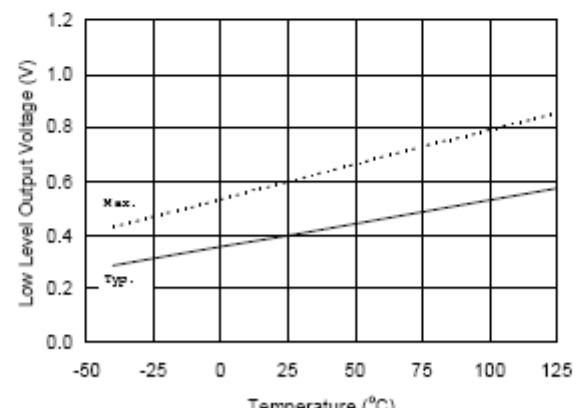
Figure 19A. Low Level Output vs. Temperature
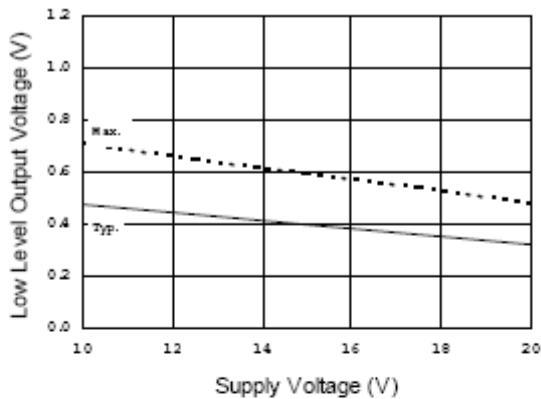
Figure 19B. Low Level Output vs. Supply Voltage
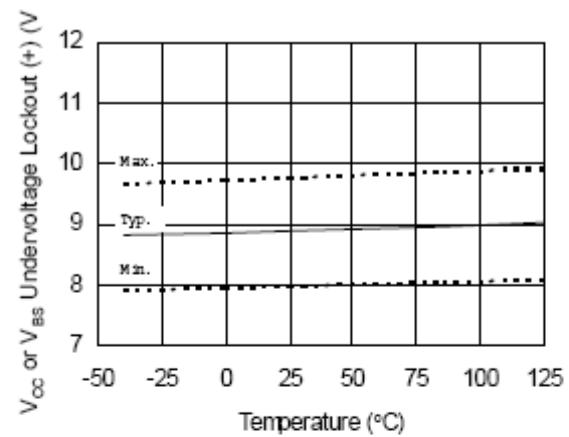
Figure 20. V_{CC} or V_{BS} Undervoltage (+)
vs. Temperature (IR2136/IR21368 Only)
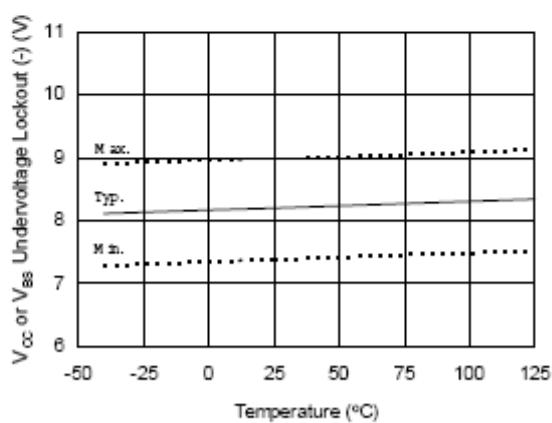
Figure 21. V_{CC} or V_{BS} Undervoltage (-)
vs. Temperature (IR2136/IR21368 Only)
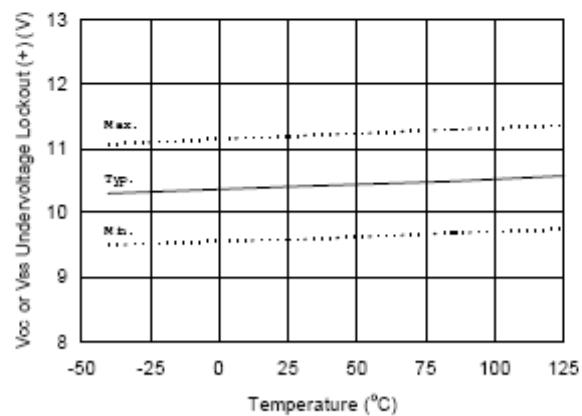
Figure 22. V_{CC} or V_{BS} Undervoltage (+) vs.
Temperature (IR21362 Only)
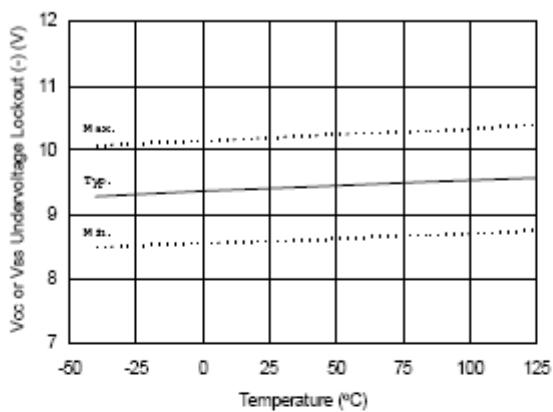
Figure 23. V$_{CC}$ or V$_{BS}$ Undervoltage (-) vs.
Temperature (IR21362 Only)
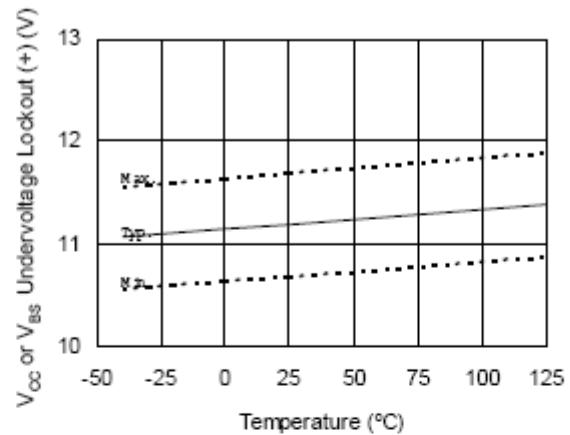
Figure 24. V$_{CC}$ or V$_{BS}$ Undervoltage (+) vs.
Temperature (IR21363/21365/IR21366/IR21367 Only)
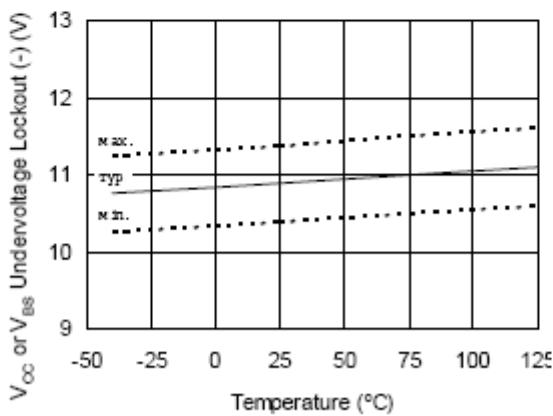
Figure 25. V$_{CC}$ or V$_{BS}$ Undervoltage (-) vs.
Temperature (IR21363/21365/IR21366/IR21367 Only)
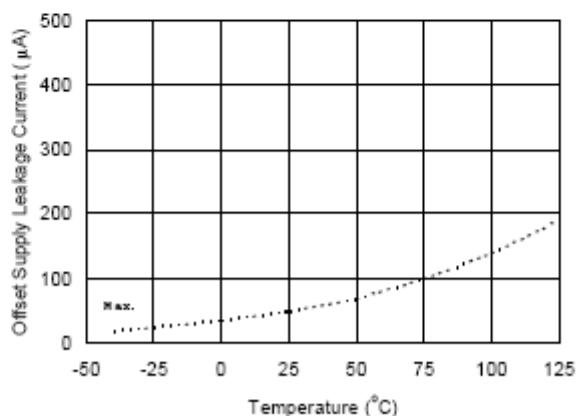
Figure 26A. Offset Supply Leakage Current vs.
Temperature
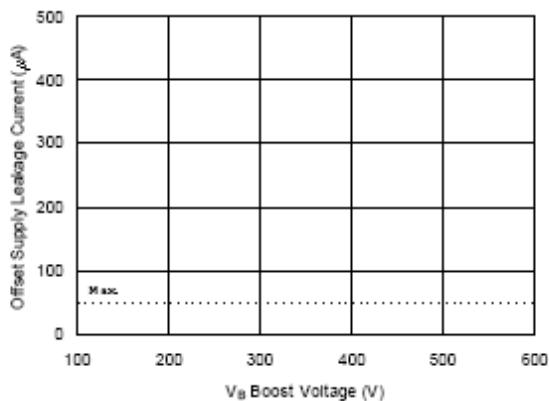
Figure 26B. Offset Supply Leakage Current vs.
V_B Boost Voltage
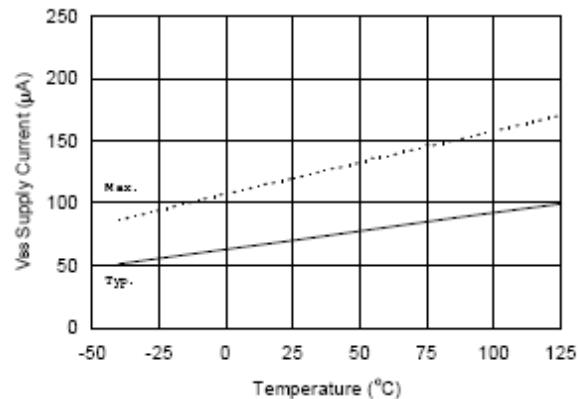
Figure 27A. V_BS Supply Current vs. Temperature
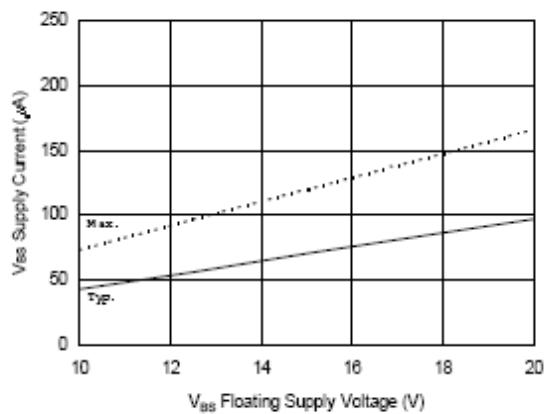
Figure 27B. V_BS Supply Current vs.
V_BS Floating Supply Voltage
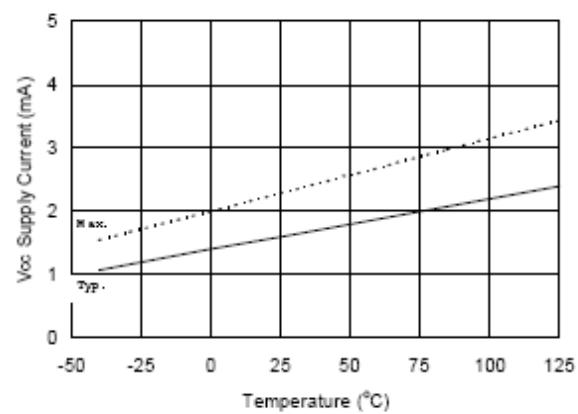
Figure 28A. V_CC Supply Current vs. Temperature
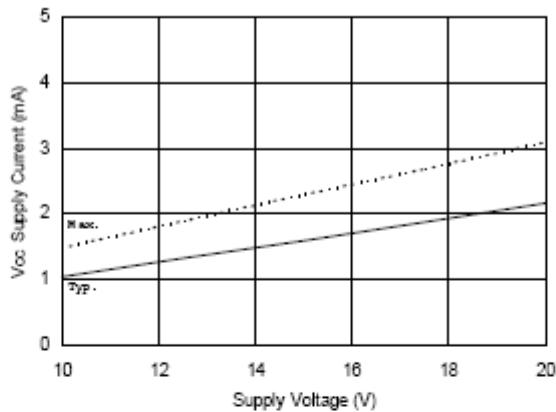
Figure 28B. V_{CC} Supply Current vs.
V_{CC} Supply Voltage
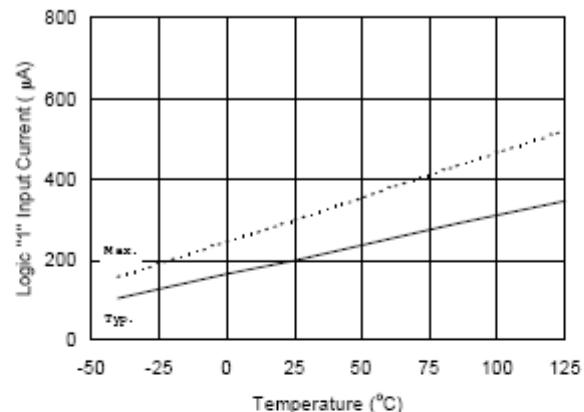
Figure 29A. Logic "1" Input Current vs. Temperature
(IR2136/21363/21365 and IR21362 Low Side Only)
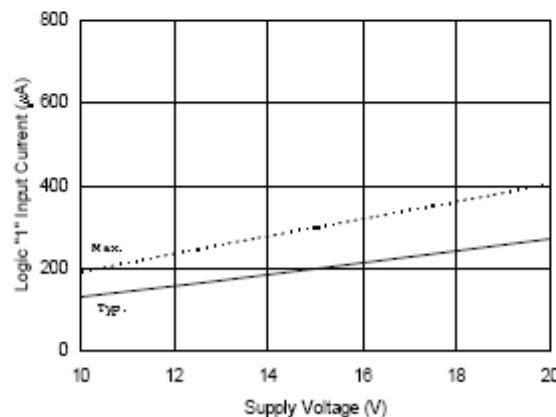
Figure 29B. Logic "1" Input Current vs. Supply Voltage
(IR2136/21363/21365 and IR21362 Low Side Only)
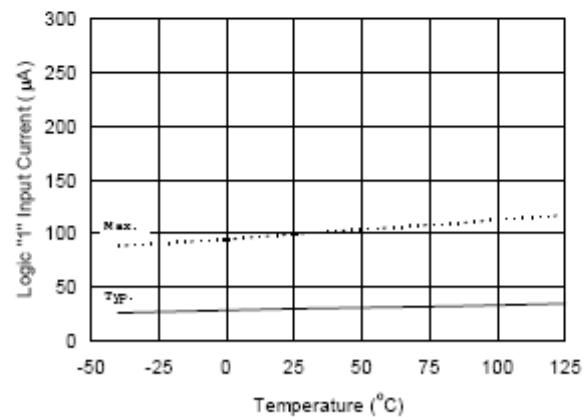
Figure 29C. Logic "1" Input Current vs.
Temperature (IR21362 High Side Only)
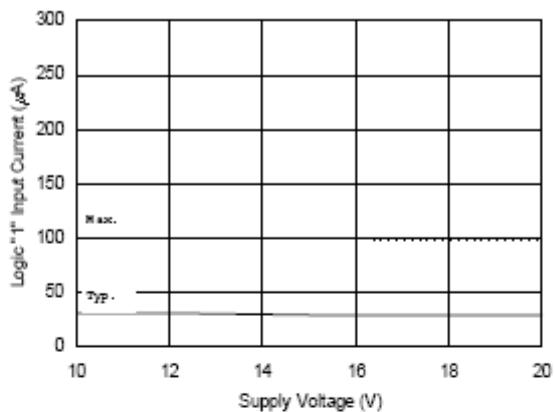
Figure 29D. Logic "1" Input Current vs.
Supply Voltage (IR21362 High Side Only)
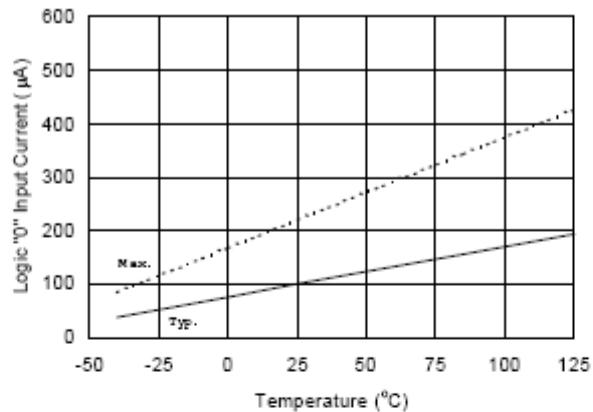
Figure 30A. Logic "0" Input Current vs. Temperature
(IR2136/21363/21365 and IR21362 Low Side Only)
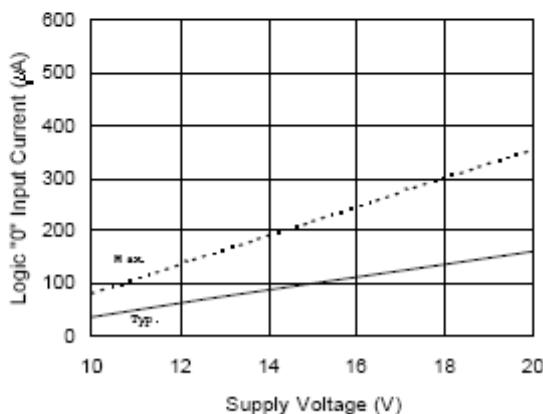
Figure 30B. Logic "0" Input Current vs. Supply
Voltage (IR2136/21363/21365 and IR21362 Low Side **Only)**
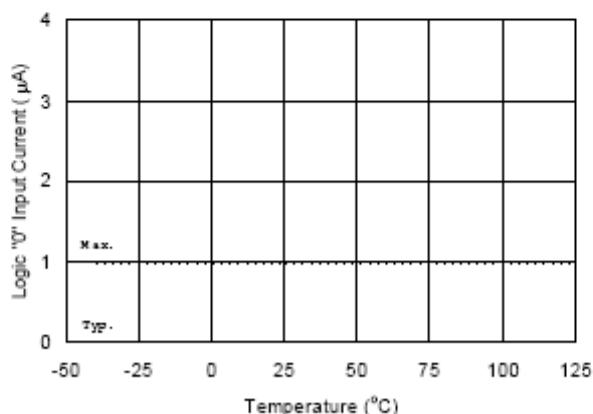
Figure 30C. Logic "0" Input Current vs.
Temperature (IR21362 High Side Only)

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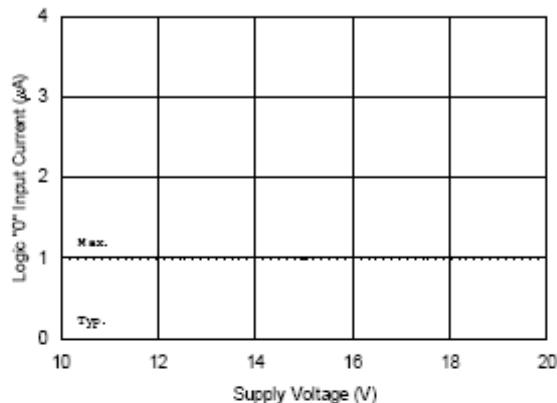
Figure 30D. Logic "0" Input Current vs.
Supply Voltage (IR21362 High Side Only)
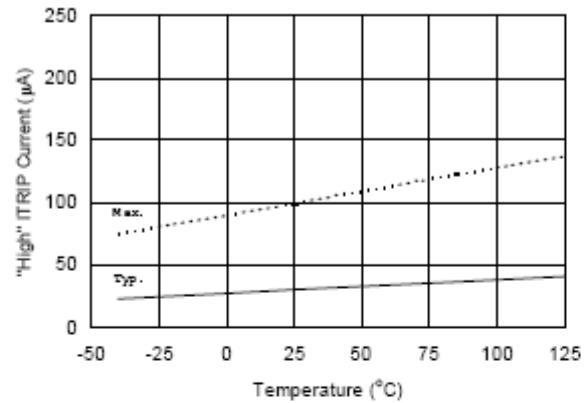
Figure 31A. "High" ITRIP Current vs. Temperature
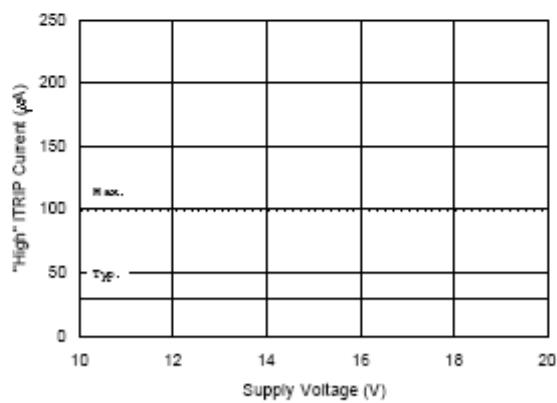
Figure 31B. "High" ITRIP Current vs. Supply Voltage
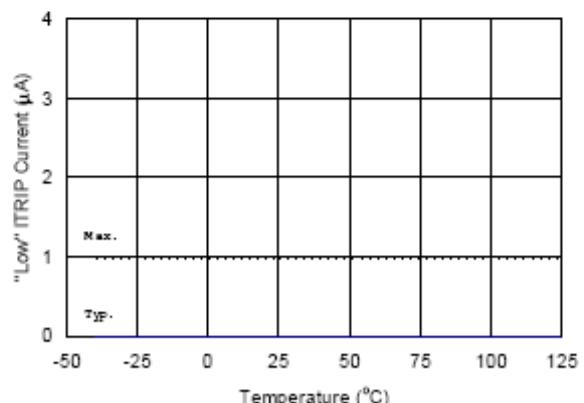
Figure 32A. "Low" ITRIP Current vs. Temperature
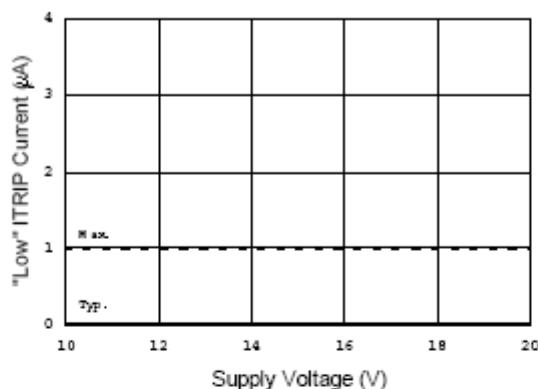
Figure 32B. "Low" ITRIP Current vs. Supply Voltage
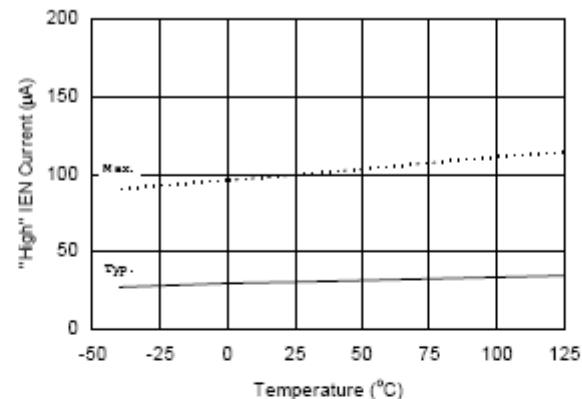
Figure 33A. "High" IEN Current vs. Temperature
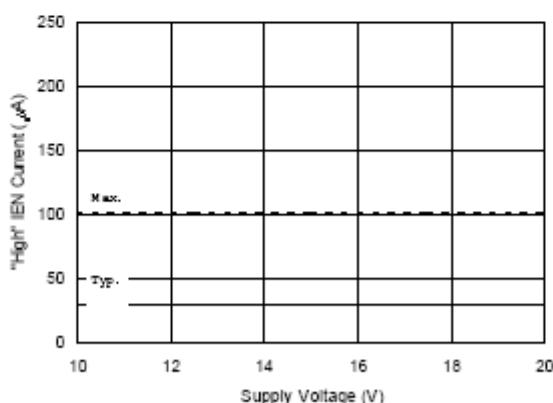

Figure 33B. "High" IEN Current vs. Supply Voltage
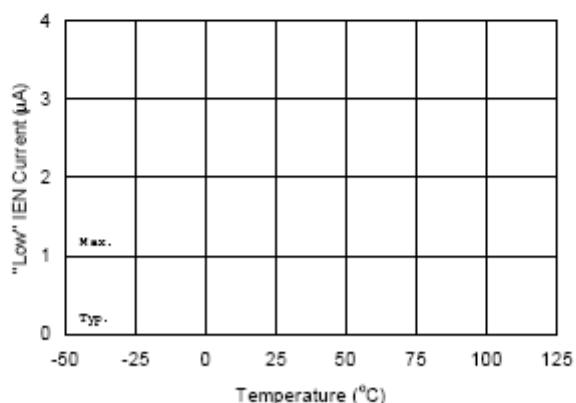

Figure 34A. "Low" IEN Current vs. Temperature
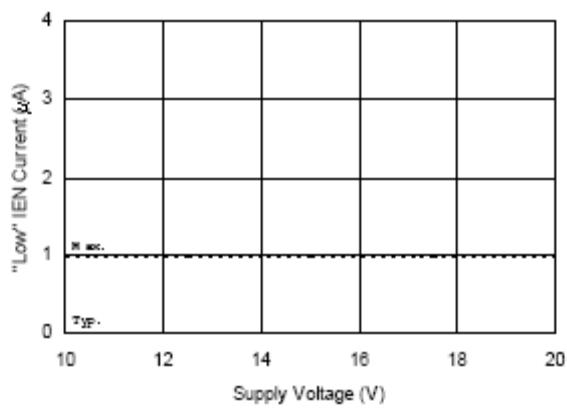
Figure 34B. "Low" IEN Current vs. Supply Voltage
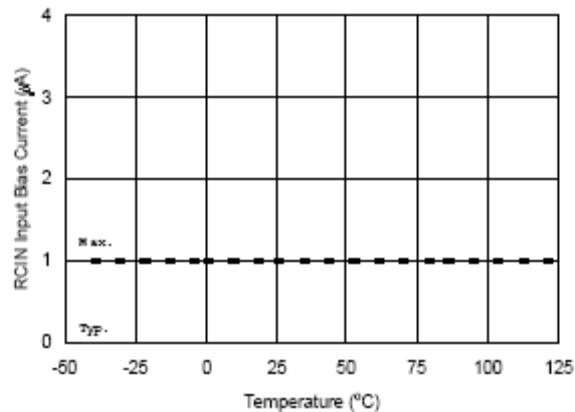
Figure 35A. RCIN Input Bias Current
vs. Temperature

Figure 34B. "Low" IEN Current vs. Supply Voltage
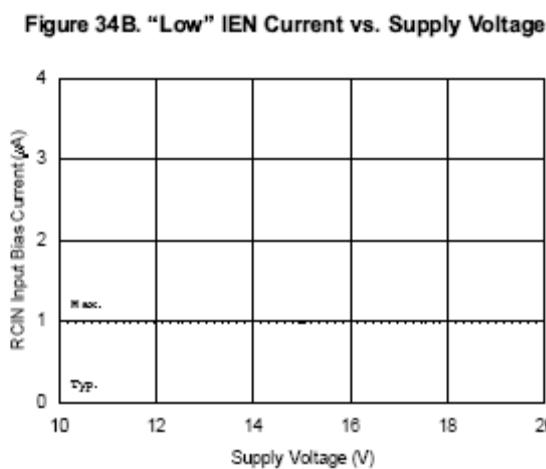
Figure 35B. RCIN Input Bias Current vs.
Supply Voltage
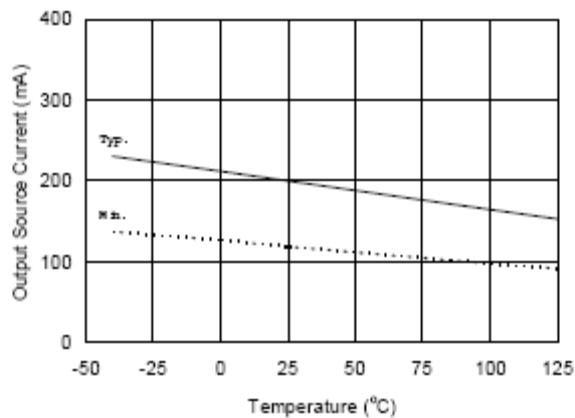
Figure 36A. Output Source Current vs.
Temperature
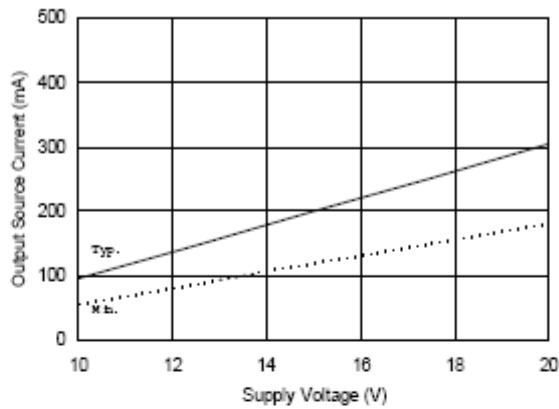
Figure 36B. Output Source Current vs.
Supply Voltage
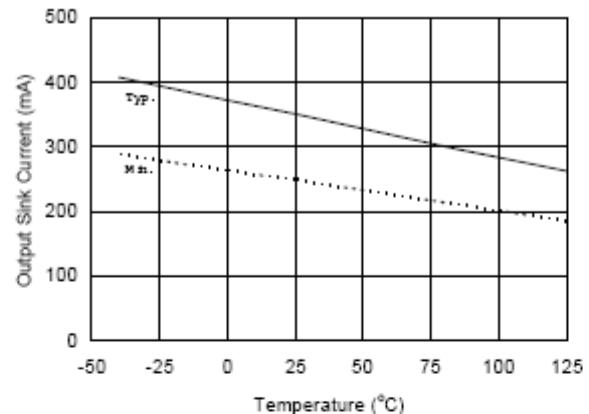
Figure 37A. Output Sink Current vs.
Temperature
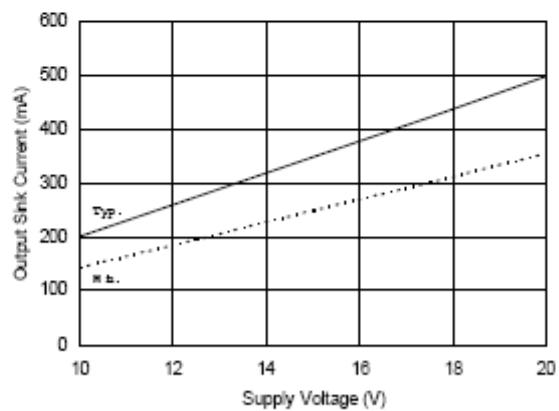
Figure 37B. Output Sink Current vs.
Supply Voltage
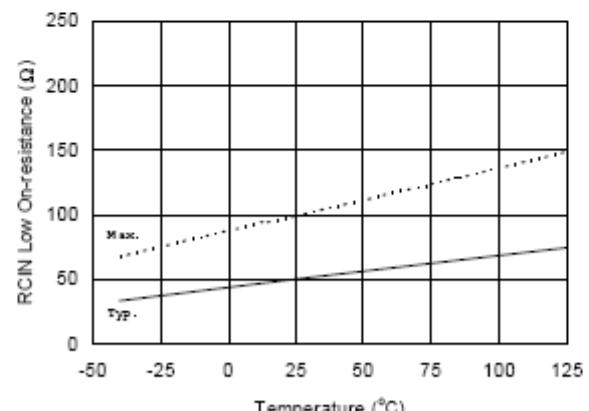
Figure 38A. RCIN Low On-resistance vs.
Temperature

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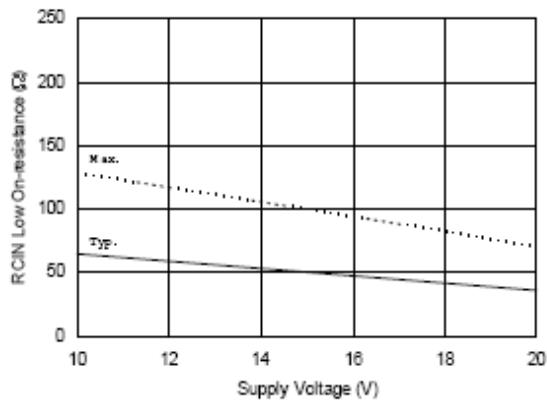
Figure 38B. RCIN Low On-resistance vs.
Supply Voltage
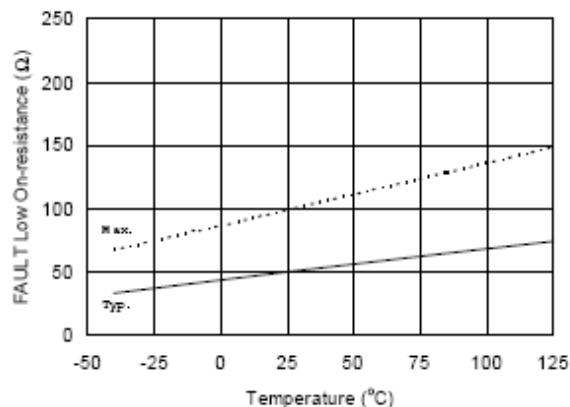
Figure 39A. FAULT Low On-resistance vs.
Temperature
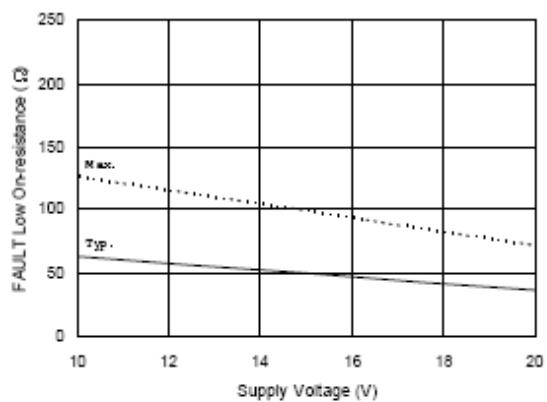
Figure 39B. FAULT Low On-resistance vs.
Supply Voltage
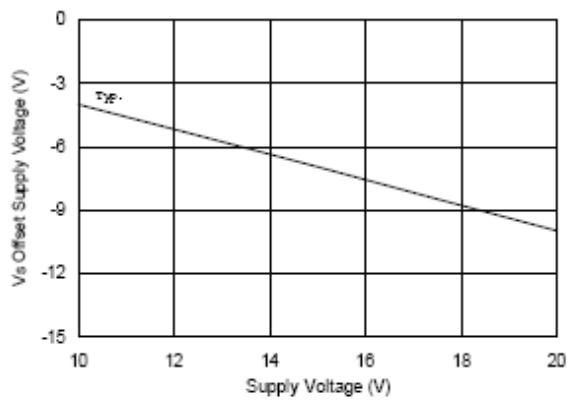
Figure 40. Maximum V_s Negative Offset vs. V_{BS}
Supply Voltage
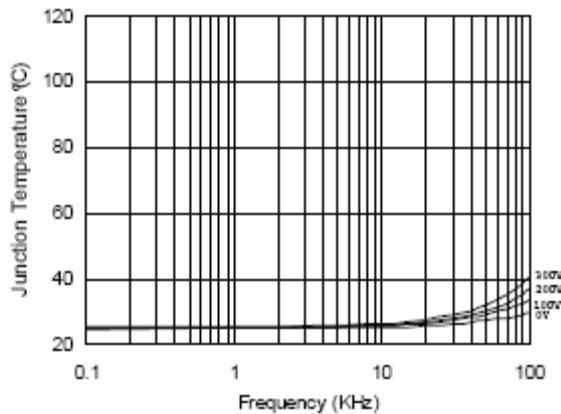
Figure 41. IR2136/IR21362(3)(5)(6)(7)(8) vs. Frequency (IRG4BC20W), Rgate=33Ω, Vcc=15V
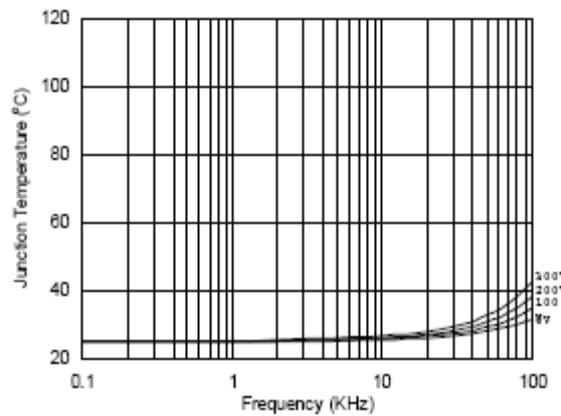
Figure 42. IR2136/IR21362(3)(5)(6)(7)(8) vs. Frequency (IRG4BC30W), Rgate=15Ω, Vcc=15V
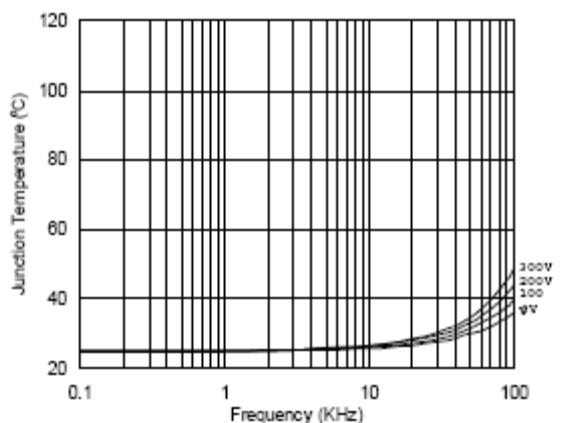
Figure 43. IR2136/IR21362(3)(5)(6)(7)(8) vs. Frequency (IRG4BC40W), Rgate=10Ω, Vcc=15V
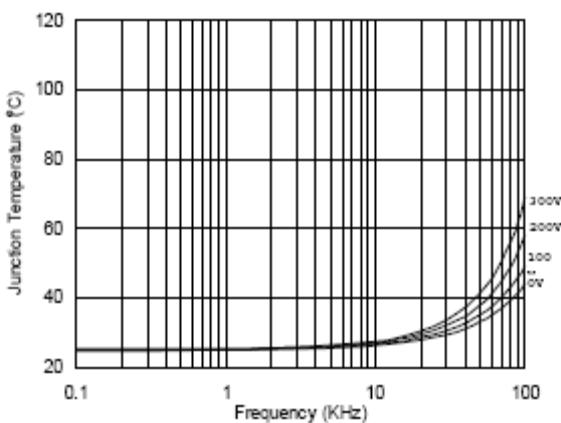
Figure 44. IR2136/IR21362(3)(5)(6)(7)(8) vs. Frequency (IRG4PC50W), Rgate=5Ω, Vcc=15V
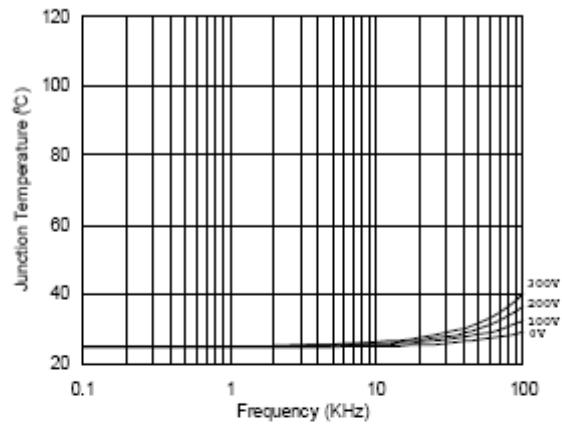
Figure 45. IR2136/IR21362(3)(5)(6)(7)(8) (J)
vs. Frequency (IRG4BC20W), Rgate=33Ω, Vcc=15V
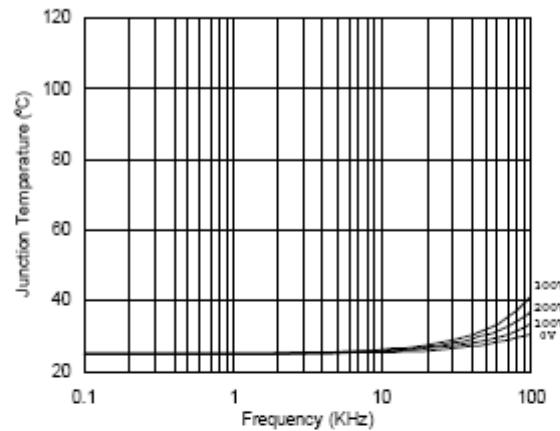
Figure 46. IR2136/IR21362(3)(5)(6)(7)(8) (J)
vs. Frequency (IRG4BC30W), Rgate=15Ω, Vcc=15V
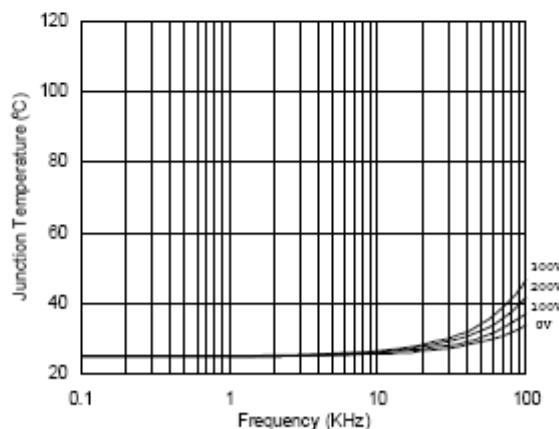
Figure 47. IR2136/IR21362(3)(5)(6)(7)(8) (J)
vs. Frequency (IRG4BC40W), Rgate=10Ω, Vcc=15V
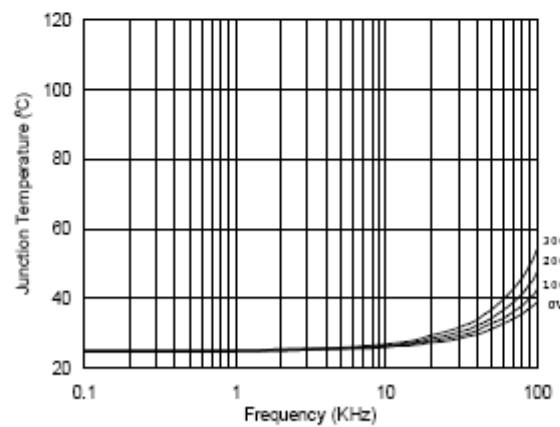
Figure 48. IR2136/IR21362(3)(5)(6)(7)(8) (J)
vs. Frequency (IRG4PC50W), Rgate=5Ω, Vcc=15V
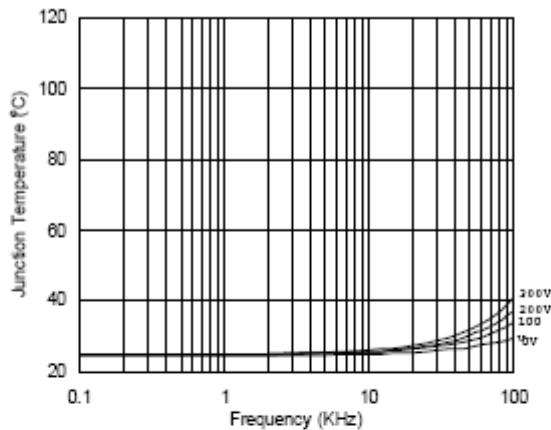
Figure 49. IR2136/IR21362(3)(5)(6)(7)(8) (S)
vs. Frequency (IRG4BC20W), Rgate=33Ω, Vcc=15V
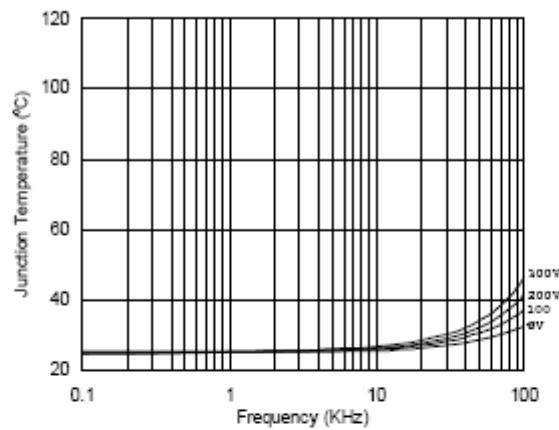
Figure 50. IR2136/IR21362(3)(5)(6)(7)(8) (S)
vs. Frequency (IRG4BC30W), Rgate=15Ω, Vcc=15V
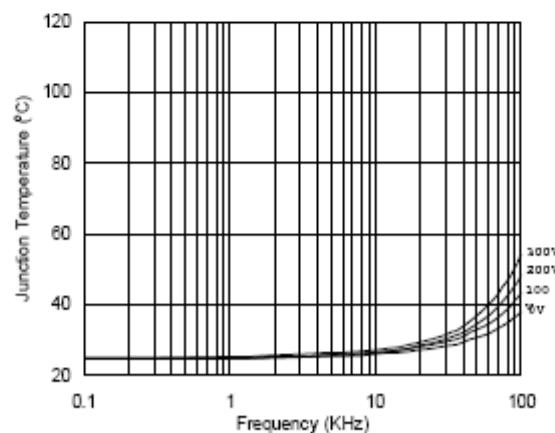

Figure 51. IR2136/IR21362(3)(5)(6)(7)(8) (S)
vs. Frequency (IRG4BC40W), Rgate=10Ω, Vcc=15V
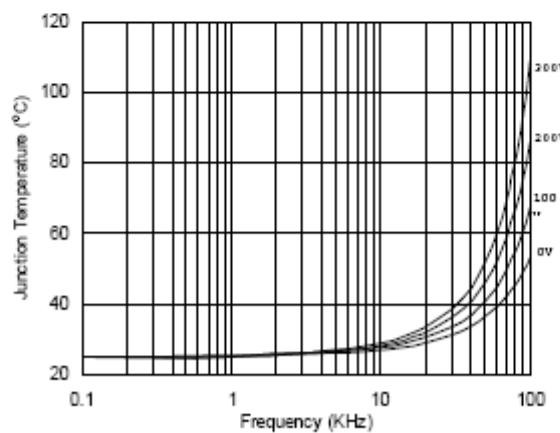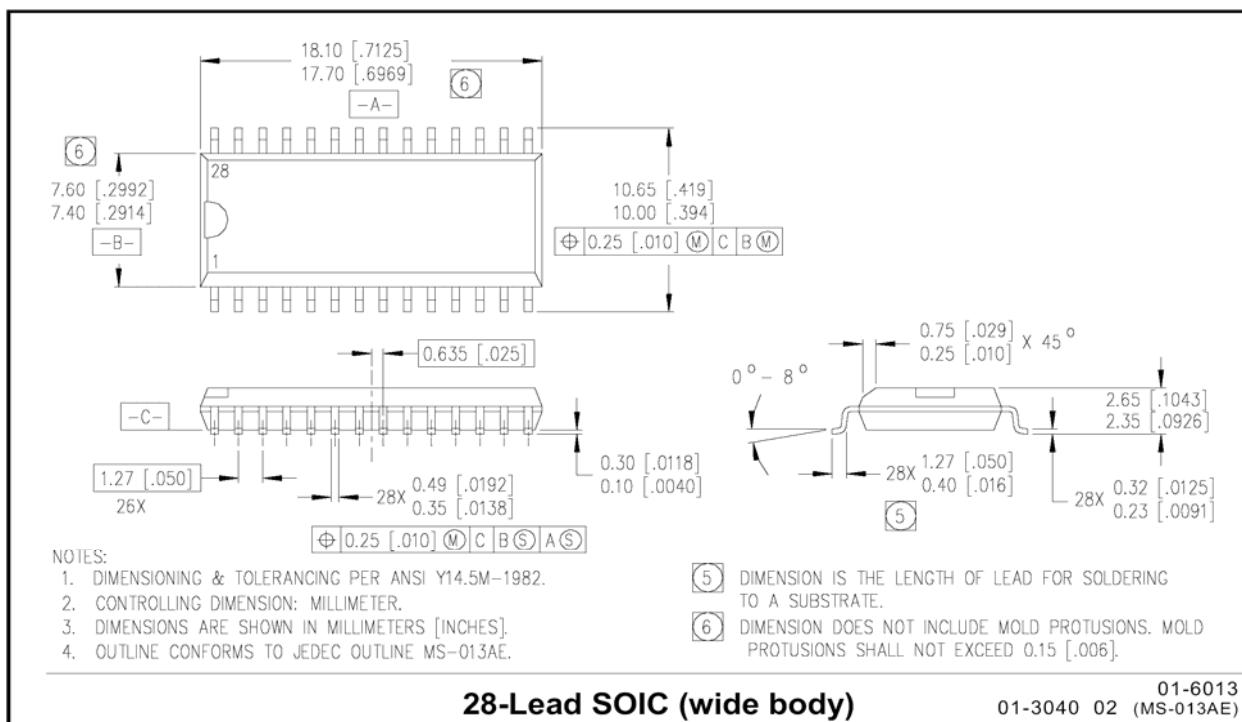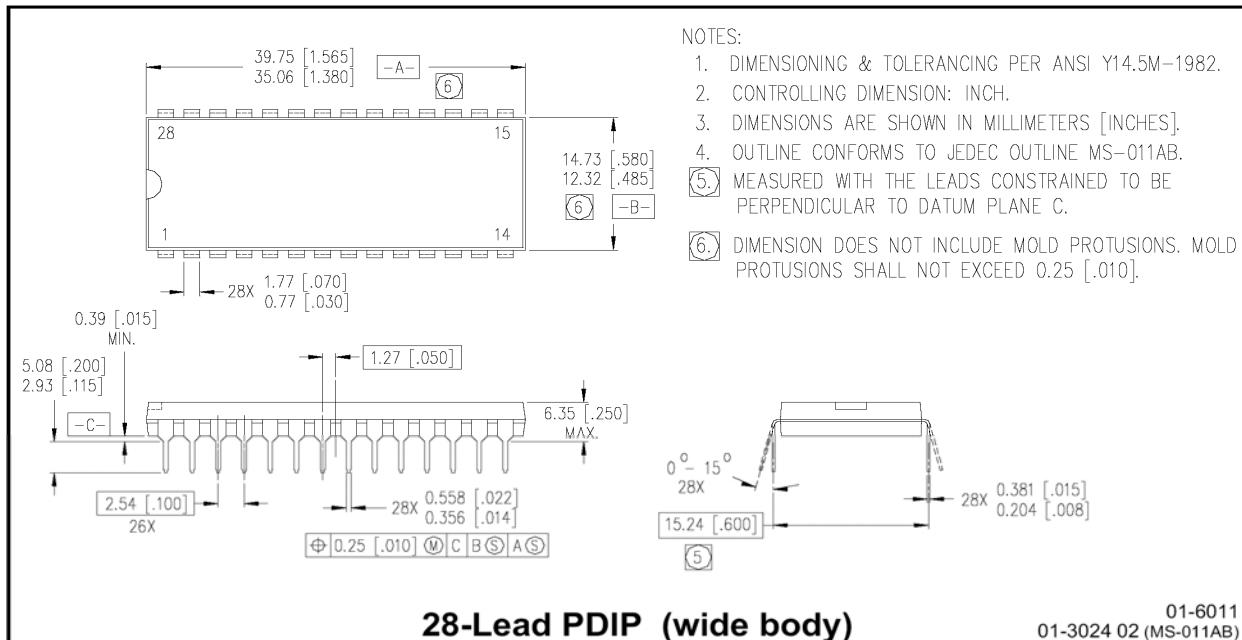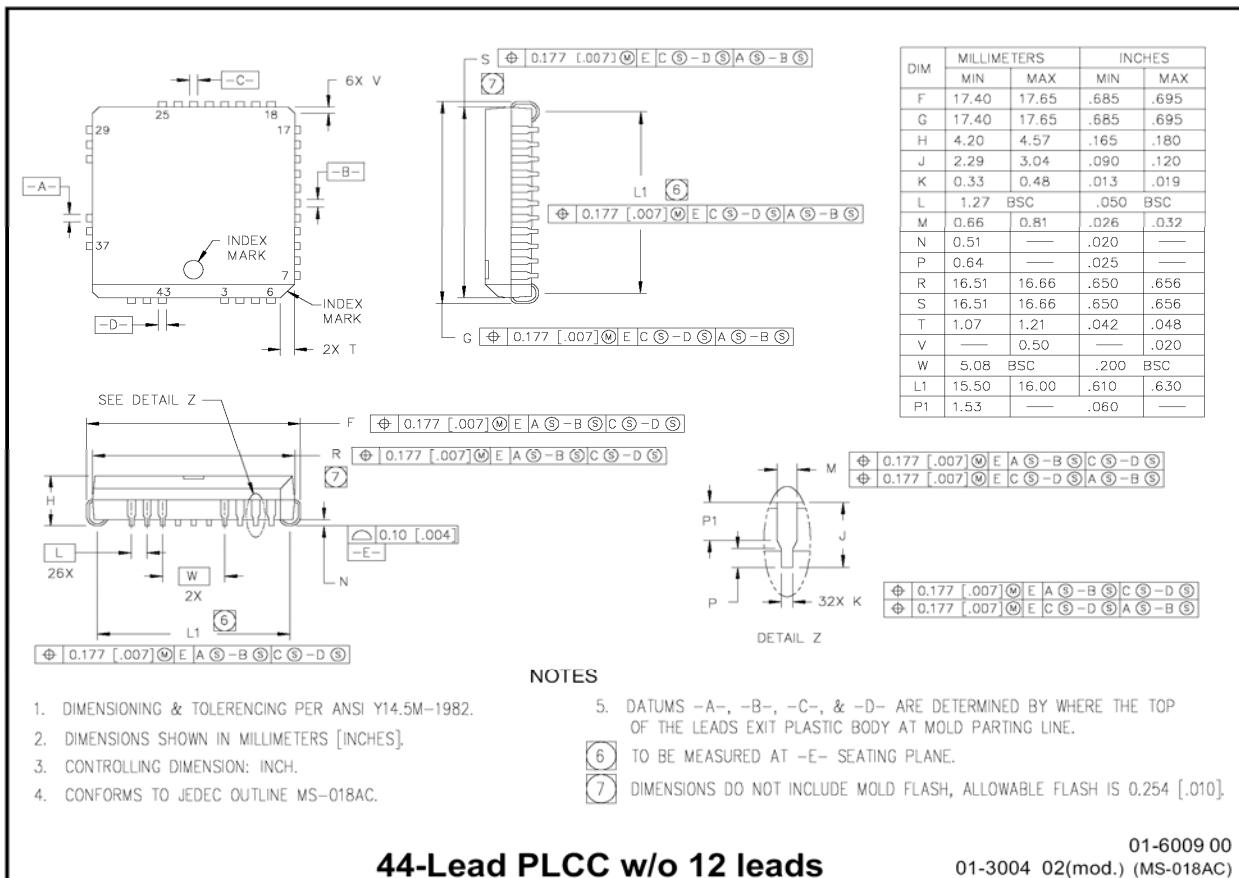
Figure 52. IR2136/IR21362(3)(5)(6)(7)(8) (S)
vs. Frequency (IRG4PC50W), Rgate=5Ω, Vcc=15V

Case Outlines

NOTES:
1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M−1982.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS−011AB.
5. MEASURED WITH THE LEADS CONSTRAINED TO BE PERPENDICULAR TO DATUM PLANE C.
6. DIMENSION DOES NOT INCLUDE MOLD PROTUSIONS. MOLD PROTUSIONS SHALL NOT EXCEED 0.25 [.010].

28-Lead PDIP (wide body)

01-6011
01-3024 02 (MS-011AB)

NOTES:
1. DIMENSIONING & TOLERANCING PER ANSI Y14.5M−1982.
2. CONTROLLING DIMENSION: MILLIMETER.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
4. OUTLINE CONFORMS TO JEDEC OUTLINE MS−013AE.

5. DIMENSION IS THE LENGTH OF LEAD FOR SOLDERING TO A SUBSTRATE.
6. DIMENSION DOES NOT INCLUDE MOLD PROTUSIONS. MOLD PROTUSIONS SHALL NOT EXCEED 0.15 [.006].

28-Lead SOIC (wide body)

01-6013
01-3040 02 (MS-013AE)

Case Outlines

DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
F	17.40	17.65	.685	.695
G	17.40	17.65	.685	.695
H	4.20	4.57	.165	.180
J	2.29	3.04	.090	.120
K	0.33	0.48	.013	.019
L	1.27 BSC		.050 BSC	
M	0.66	0.81	.026	.032
N	0.51	——	.020	——
P	0.64	——	.025	——
R	16.51	16.66	.650	.656
S	16.51	16.66	.650	.656
T	1.07	1.21	.042	.048
V	——	0.50	——	.020
W	5.08 BSC		.200 BSC	
L1	15.50	16.00	.610	.630
P1	1.53	——	.060	——

NOTES

1. DIMENSIONING & TOLERENCING PER ANSI Y14.5M-1982.
2. DIMENSIONS SHOWN IN MILLIMETERS [INCHES].
3. CONTROLLING DIMENSION: INCH.
4. CONFORMS TO JEDEC OUTLINE MS-018AC.

5. DATUMS -A-, -B-, -C-, & -D- ARE DETERMINED BY WHERE THE TOP OF THE LEADS EXIT PLASTIC BODY AT MOLD PARTING LINE.
6. TO BE MEASURED AT -E- SEATING PLANE.
7. DIMENSIONS DO NOT INCLUDE MOLD FLASH, ALLOWABLE FLASH IS 0.254 [.010].

44-Lead PLCC w/o 12 leads

01-6009 00
01-3004 02(mod.) (MS-018AC)

LEAD-FREE PART MARKING INFORMATION

Part number —— **IRSxxxxx**

Date code —— **YWW?** IOR —— IR logo

Pin 1 Identifier ● **?XXXX**

Lot Code (Prod mode – 4 digit SPN code)

?	MARKING CODE
P	Lead Free Released
	Non-Lead Free Relased

Assembly site code Per SCOP 200-002

ORDER INFORMATION

Basic Part
28-Lead PDIP IR2136(3,5,6,7,8)
28-Lead SOIC IR2136(3,5,6,7,8)S
44-Lead PLCC IR2136(3,5,6,7,8)J
28-Lead PDIP IR21362
28-Lead SOIC IR21362S
44-Lead PLCC IR21362J

Order IR2136(3,5,6,7,8)
Order IR2136(3,5,6,7,8)S
Order IR2136(3,5,6,7,8)J
Order IR21362
Order IR21362S
Order IR21362J

Lead-Free Part
28-Lead PDIP IR2136(3,5,6,7,8)
28-Lead SOIC IR2136(3,5,6,7,8)S
44-Lead PLCC IR2136(3,5,6,7,8)J
28-Lead PDIP IR21362
28-Lead SOIC IR21362S
44-Lead PLCC IR21362J

Order IR2136(3,5,6,7,8)PbF
Order IR2136(3,5,6,7,8)(S)PbF
Order IR2136(3,5,6,7,8)(J)PbF
Order IR21362PbF
Order IR21362SPbF
Order IR21362JPbF

International **IOR** Rectifier